

TUSB4020BI 双端口 USB 2.0 集线器

1 特性

- 双端口 USB 2.0 集线器
- USB 2.0 集线器特性：
 - 多事务转换器 (MTT) 集线器：两个事务转换器
 - 每个事务转换器具有四个异步端点缓冲器
- 兼容 Type C
- 支持电池充电
 - CDP 模式 (上行端口已连接)
 - DCP 模式 (上行端口未连接)
 - DCP 模式符合中国电信行业标准 YD/T 1591-2009
 - D+/D- 分压器模式
- 支持每端口或成组电源开关以及过流通知输入
- OTP ROM、串行 EEPROM 或 I²C/SMBus 目标接口可实现定制配置：
 - VID 和 PID
 - 端口定制
 - 制造商和产品字符串 (非通过 OTP ROM)
 - 序列号 (非通过 OTP ROM)
- 可使用端子选择、EEPROM 或 I²C/SMBus 目标接口选择应用特性
- 提供 128 位通用唯一标识符 (UUID)
- 支持通过 USB 2.0 上行端口进行板载和系统内 OTP/EEPROM 编程
- 单个时钟输入、24MHz 晶体或晶振
- 无特殊驱动程序要求；可与任一支持 USB 堆叠的操作系统无缝工作
- 48 引脚 HTQFP 封装 (PHP)

2 应用

- 计算机系统
- [扩展坞](#)
- [监控器](#)
- 机顶盒

3 说明

TUSB4020BI 是一款双端口 USB 2.0 集线器，该集线器在上行端口上提供 USB 高速/全速连接，在两个下行端口上提供 USB 高速、全速或低速连接。当上行端口被连接至一个支持高速和全速/低速连接的电气环境中时，下行端口上的高速和全速/低速 USB 连接被启用。当上行端口被连接到一个只支持全速/低速连接的电气环境中时，下行端口上的高速连接被禁用。

TUSB4020BI 支持每端口或者成组电源开关和过流保护。

按照 USB 主机的要求，一个端口电源单独控制集线器开关为每个下行端口上电或者断电。另外，当端口电源单独控制型集线器检测到过流事件时，仅关闭受影响下行端口的电源。

当需要为任一端口供电时，成组集线器将开启所有下行端口的电源。只有当所有端口处于电源可被移除的状态时，到下行端口的电源才可被关闭。此外，当成组集线器检测到过流事件时，将关闭所有下行端口的电源。

TUSB4020BI 下行端口可提供电池充电下行端口 (CDP) 握手支持，从而为电池充电应用提供支持。未连接上行端口时，该器件还支持专用充电端口 (DCP) 模式。DCP 模式支持 USB 电池充电并且符合中国电信行业标准 YD/T 1591-2009，能够为 USB 器件提供支持。此外，未连接上行端口时，自动模式能够为 BC 器件以及支持分压器模式充电解决方案的器件提供透明支持。



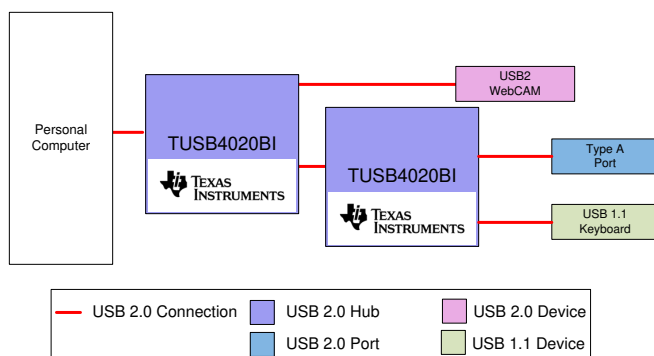
TUSB4020BI 能够为一些特性（包括电池充电支持）提供端子 strap 配置，还能够通过 OTP ROM、I²C EEPROM 或 I²C/SMBus 目标接口为 PID、VID、自定义端口和物理层配置提供定制服务。使用 I²C EEPROM 或 I²C/SMBus 目标接口时，还可以提供定制字符串支持。

该器件采用 48 引脚耐热增强型薄型四方扁平 (HTQFP) 封装，工业版的工作温度范围为 -40°C 到 85°C。

封装信息

| 器件型号 | 封装 ⁽¹⁾ | 封装尺寸 ⁽²⁾ |
|------------|-------------------|---------------------|
| TUSB4020BI | PHP (HTQFP, 48) | 9mm × 9mm |

- (1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。
(2) 封装尺寸（长 × 宽）为标称值，并包括引脚（如适用）。



方框图

Table of Contents

| | | | |
|---|-----------|--|-----------|
| 1 特性 | 1 | 6.5 Programming..... | 13 |
| 2 应用 | 1 | 6.6 Register Maps..... | 14 |
| 3 说明 | 1 | 7 Application and Implementation | 26 |
| 4 Pin Configuration and Functions | 4 | 7.1 Application Information..... | 26 |
| 5 Specifications | 7 | 7.2 Typical Applications..... | 27 |
| 5.1 Absolute Maximum Ratings ⁽¹⁾ | 7 | 7.3 Power Supply Recommendations..... | 31 |
| 5.2 ESD Ratings..... | 7 | 7.4 Layout..... | 32 |
| 5.3 Recommended Operating Conditions..... | 7 | 8 Device and Documentation Support | 35 |
| 5.4 Thermal Information..... | 7 | 8.1 Documentation Support..... | 35 |
| 5.5 3.3V I/O Electrical Characteristics..... | 8 | 8.2 接收文档更新通知..... | 35 |
| 5.6 Hub Input Supply Current..... | 8 | 8.3 支持资源..... | 35 |
| 5.7 Power-Up Timing Requirements..... | 9 | 8.4 Trademarks..... | 35 |
| 6 Detailed Description | 10 | 8.5 静电放电警告..... | 35 |
| 6.1 Overview..... | 10 | 8.6 术语表..... | 35 |
| 6.2 Functional Block Diagram..... | 10 | 9 Revision History | 35 |
| 6.3 Feature Description..... | 11 | 10 Mechanical, Packaging, and Orderable Information | 36 |
| 6.4 Device Functional Modes..... | 12 | | |

4 Pin Configuration and Functions

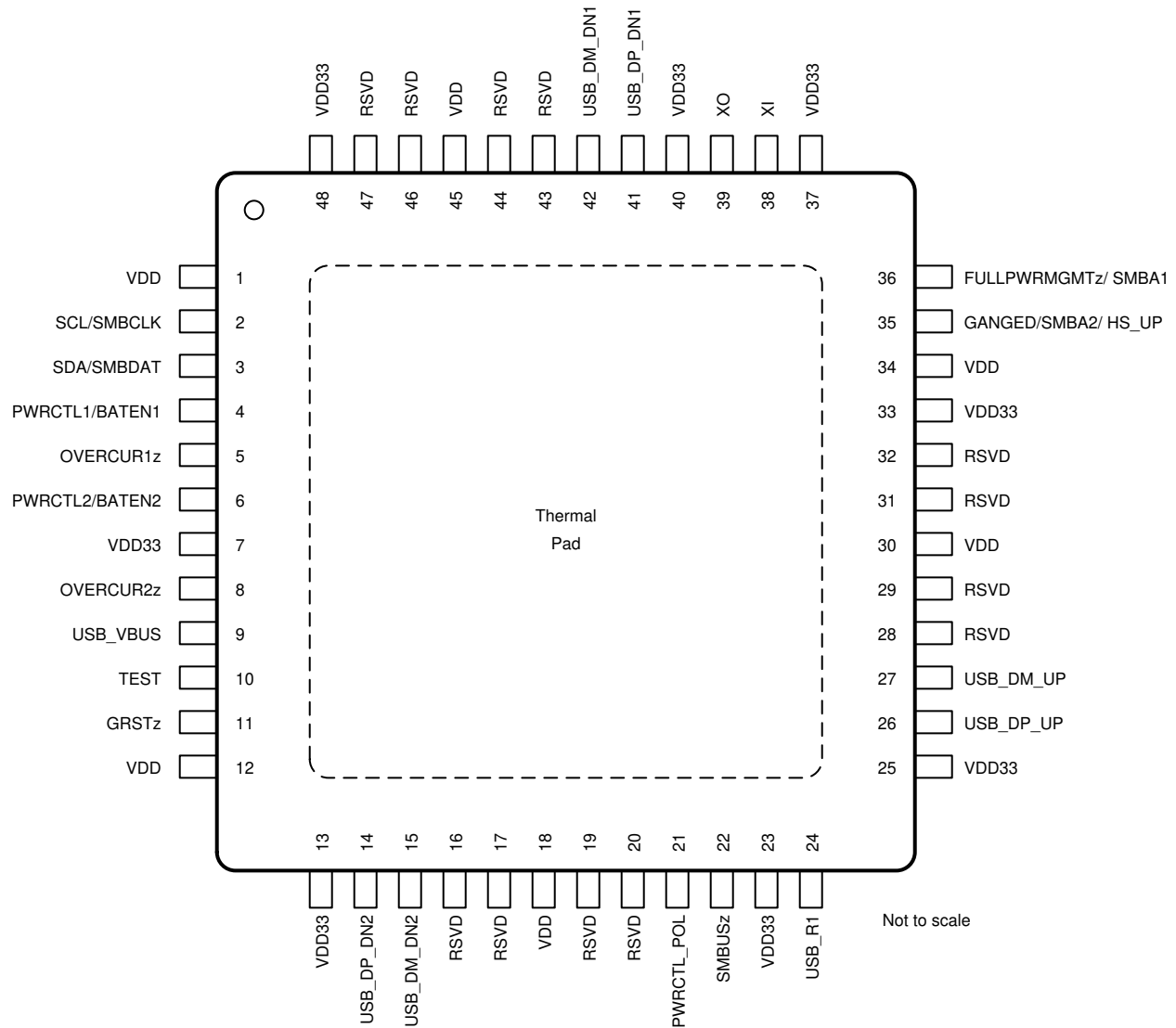


图 4-1. PHP Package, 48-Pin HTQFP (Top View)

表 4-1. Pin Functions

| PIN | | TYPE ⁽¹⁾ | DESCRIPTION |
|--------------------------------|-----|---------------------|---|
| NAME | NO. | | |
| CLOCK AND RESET SIGNALS | | | |
| GRSTz | 11 | I PU | Global power reset. This reset brings all of the TUSB4020BI internal registers back to the default state. When GRSTz is asserted, the device is completely nonfunctional. |
| XI | 38 | I | Crystal input. This terminal is the crystal input for the internal oscillator. The input can alternately be driven by the output of an external oscillator. |
| XO | 39 | O | Crystal output. This terminal is the crystal output for the internal oscillator. If XI is driven by an external oscillator this pin can be left unconnected. |
| USB UPSTREAM SIGNALS | | | |
| USB_DP_UP | 26 | I/O | USB high-speed differential transceiver (positive) |
| USB_DM_UP | 27 | I/O | USB high-speed differential transceiver (negative) |
| USB_R1 | 24 | I | Precision resistor reference. Connect a 9.53kΩ ±1% resistor between USB_R1 and GND. |

表 4-1. Pin Functions (续)

| PIN | | TYPE ⁽¹⁾ | DESCRIPTION |
|-------------------------------------|-----|---------------------|---|
| NAME | NO. | | |
| USB_VBUS | 9 | I | USB upstream port power monitor. The VBUS detection requires a voltage divider. The signal USB_VBUS must be connected to VBUS through a 90.9kΩ ±1% resistor and to ground through a 10kΩ ±1% resistor from the signal to ground. |
| USB DOWNSTREAM SIGNALS | | | |
| USB_DP_DN1 | 41 | I/O | USB high-speed differential transceiver (positive) downstream port 1. |
| USB_DM_DN1 | 42 | I/O | USB high-speed differential transceiver (negative) downstream port 1. |
| PWRCTL1/BATEN1 | 4 | I/O PD | USB port 1 power-on control for downstream power or battery charging enable. The terminal is used for control of the downstream power switch for Port 1. In addition, the value of the terminal is sampled at the deassertion of reset to determine the value of the battery charging support for Port 1 as indicated in the Battery Charging Support register. 0 = Battery charging not supported 1 = Battery charging supported |
| OVERCUR1z | 5 | I PU | USB DS port 1 overcurrent detection input. This terminal is used to connect the overcurrent output of the downstream port power switch for port 1. 0 = An overcurrent event has occurred 1 = An overcurrent event has not occurred If power management is enabled, review the power switch to determine the required external circuitry. In ganged mode, either OVERCUR1z or OVERCUR2z can be used. In ganged mode, the overcurrent is reported as a hub event instead of a port event. |
| USB_DP_DN2 | 14 | I/O | USB high-speed differential transceiver (positive) downstream port 2. |
| USB_DM_DN2 | 15 | I/O | USB high-speed differential transceiver (negative) downstream port 2. |
| PWRCTL2/BATEN2 | 6 | I/O PD | Power-on control /battery charging enable for downstream port 2. This terminal is used for control of the downstream power switch for port 2. The value of the terminal is sampled at the deassertion of reset to determine the value of the battery charging support for port 2 as indicated in the Battery Charging Support register. 0 = Battery charging not supported 1 = Battery charging supported |
| OVERCUR2z | 8 | I PU | Overcurrent detection for downstream port 2. This terminal is used to connect the over current output of the downstream port power switch for port 2. 0 = An overcurrent event has occurred 1 = An overcurrent event has not occurred If power management is enabled, review the power switch to determine the required external circuitry. In ganged mode either OVERCUR1z or OVERCUR2z can be used. In ganged mode the overcurrent is reported as a hub event instead of a port event. |
| I²C/SMBUS SIGNALS | | | |
| SCL/SMBCLK | 2 | I/O PD | I ² C clock/SMBus clock. Function of terminal depends on the setting of the SMBUSz input. When SMBUSz = 1, this terminal acts as the serial clock interface for an I ² C EEPROM. When SMBUSz = 0, this terminal acts as the serial clock interface for an SMBus host. This pin must be pulled up to use the OTP ROM. Can be left unconnected if external interface not implemented. |
| SDA/SMBDAT | 3 | I/O PD | I ² C data/SMBus data. Function of terminal depends on the setting of the SMBUSz input. When SMBUSz = 1, this terminal acts as the serial data interface for an I ² C EEPROM. When SMBUSz = 0, this terminal acts as the serial data interface for an SMBus host. This pin must be pulled up to use the OTP ROM. Can be left unconnected if external interface not implemented. |

表 4-1. Pin Functions (续)

| PIN | | TYPE ⁽¹⁾ | DESCRIPTION |
|---------------------------------------|---|---------------------|---|
| NAME | NO. | | |
| TEST AND MISCELLANEOUS SIGNALS | | | |
| SMBUSz | 22 | I PU | <p>SMBUS mode.</p> <p>The value of the terminal is sampled at the deassertion of reset to enable I²C or SMBus mode.</p> <p>0 = SMBus mode selected 1 = I²C mode selected</p> <p>After reset, this signal is driven low by the TUSB4020BI. Due to this behavior, TI recommends to not tie directly to supply but instead pull up or pull down using external resistor.</p> |
| PWRCTL_POL | 21 | I/O PD | <p>Power control polarity.</p> <p>The value of the terminal is sampled at the deassertion of reset to set the polarity of PWRCTL[2:1].</p> <p>0 = PWRCTL polarity is active high. 1 = PWRCTL polarity is active low.</p> <p>After reset, this signal is driven low by the TUSB4020BI. Due to this behavior, TI recommends to not tie directly to supply but instead pull up or pull down using external resistor.</p> |
| GANGED/SMBA2/ HS_UP | 35 | I PU | <p>Ganged operation enable/SMBus address bit 2/ high-speed status for upstream port</p> <p>The value of the terminal is sampled at the deassertion of reset to set the power switch and over current detection mode as follows:</p> <p>0 = Individual power control supported when power switching is enabled. 1 = Power control gangs supported when power switching is enabled.</p> <p>When SMBus mode is enabled using SMBUSz, this terminal sets the value of the SMBus target address bit 2. SMBus target address bit 3 is always 1 for the TUSB4020BI.</p> <p>After reset, this signal indicates the high-speed USB connection status of the upstream port. A value of 1 indicates the upstream port is connected to a high-speed USB capable port.</p> <p>Note: individual power control must be enabled for battery charging applications.</p> |
| FULLPWRMGMTz/ SMBA1 | 36 | I, PU | <p>Full power management enable/ SMBus Address bit 1.</p> <p>The value of the terminal is sampled at the deassertion of reset to set the power switch control follows:</p> <p>0 = Power switching supported 1 = Power switching not supported</p> <p>Full power management is the ability to control power to the downstream ports of the TUSB4020BI using PWRCTL[2:1]/BATEN[2:1].</p> <p>When SMBus mode is enabled using SMBUSz, this terminal sets the value of the SMBus target address bit 1. SMBus target address bit 3 is always 1 for the TUSB4020BI.</p> <p>Can be left unconnected if full power management and SMBus are not implemented.</p> <p>After reset, this signal is driven low by the TUSB4020BI. Due to this behavior, TI recommends to not tie directly to supply but instead pull up or pull down using external resistor.</p> <p>Note: power switching must be supported for battery charging applications.</p> |
| RSVD | 16, 17, 19, 20, 28, 29, 31, 32, 43, 44, 46, 47 | I/O | Reserved. These pins are for internal use only and must be left unconnected on PCB. |
| TEST | 10 | I PD | TEST mode enable. When this terminal is asserted high at reset enables test mode. This terminal is reserved for factory use. TI recommends to pull down this terminal to ground. |
| POWER AND GROUND SIGNALS | | | |
| VDD | 1, 12, 18, 30, 34, 45 | PWR | 1.1V power rail |
| VDD33 | 7, 13, 23, 25, 33, 37, 40, 48 | PWR | 3.3V power rail |
| GND | PAD | — | Ground |

(1) I = input, O = output, I/O = input/output, PU = internal pullup resistor, PD = internal pulldown resistor, and PWR = power signal

5 Specifications

5.1 Absolute Maximum Ratings ⁽¹⁾

over operating free-air temperature (unless otherwise noted)

| | | MIN | MAX | UNIT |
|------------------|---|-------|------|------|
| Supply Voltage | V _{DD} Steady-state supply voltage | - 0.3 | 1.4 | V |
| | V _{DD33} Steady-state supply voltage | - 0.3 | 3.8 | V |
| Voltage | USB_VBUS pin | - 0.3 | 1.4 | V |
| | XI and XO pins | - 0.4 | 2.45 | V |
| | All other pins | - 0.3 | 3.8 | V |
| T _J | Operating junction temperature | - 40 | 125 | °C |
| T _{stg} | Storage temperature | - 65 | 150 | °C |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

5.2 ESD Ratings

| | | | VALUE | UNIT |
|--------------------|-------------------------|---|-------|------|
| V _(ESD) | Electrostatic discharge | Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾ | ±4000 | V |
| | | Charged device model (CDM), per ANSI/ESDA/JEDEC JS-002, all pins ⁽²⁾ | ±1500 | |

- (1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.
 (2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

| | | MIN | NOM | MAX | UNIT |
|--------------------|--------------------------------------|--------|-----|-------|------|
| VDD ⁽¹⁾ | 1.1V supply voltage | 0.99 | 1.1 | 1.26 | V |
| VDD33 | 3.3V supply voltage | 3 | 3.3 | 3.6 | V |
| USB_VBUS | Voltage at USB_VBUS pin | 0 | | 1.155 | V |
| XI, XO | Voltage at XI and XO pin | - 0.35 | | 1.98 | V |
| T _A | Operating free-air temperature range | - 40 | 25 | 85 | °C |
| T _J | Operating junction temperature range | - 40 | 25 | 105 | °C |

- (1) A 1.05V, 1.1V, or 1.2V supply can be used as long as minimum and maximum supply conditions are met.

5.4 Thermal Information

| THERMAL METRIC ⁽¹⁾ | | TUSB4020BI | UNIT |
|-------------------------------|--|-------------|------|
| | | PHP (HTQFP) | |
| | | 48 PINS | |
| R _{θ JA} | Junction-to-ambient thermal resistance | 31.8 | °C/W |
| R _{θ JC(top)} | Junction-to-case (top) thermal resistance | 16.1 | °C/W |
| R _{θ JB} | Junction-to-board thermal resistance | 13 | °C/W |
| ψ _{JT} | Junction-to-top characterization parameter | 0.5 | °C/W |
| ψ _{JB} | Junction-to-board characterization parameter | 12.9 | °C/W |
| R _{θ JC(bot)} | Junction-to-case (bottom) thermal resistance | 0.9 | °C/W |

- (1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

5.5 3.3V I/O Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

| PARAMETER | | OPERATION | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|------------------|---|-----------|-----------------------------|-----|-----|--------------|------|
| V _{IH} | High-level input voltage ⁽¹⁾ | VDD33 | | 2 | | VDD33 | V |
| V _{IL} | Low-level input voltage ⁽¹⁾ | VDD33 | | 0 | | 0.8 | V |
| V _I | Input voltage | | | 0 | | VDD33 | V |
| V _O | Output voltage ⁽²⁾ | | | 0 | | VDD33 | V |
| t _t | Input transition time (t _{rise} and t _{fall}) | | | 0 | | 25 | ns |
| V _{hys} | Input hysteresis ⁽³⁾ | | | | | 0.13 × VDD33 | V |
| V _{OH} | High-level output voltage | VDD33 | I _{OH} = -4mA | 2.4 | | | V |
| V _{OL} | Low-level output voltage | VDD33 | I _{OL} = 4mA | | | 0.4 | V |
| I _{OZ} | High-impedance, output current ⁽²⁾ | VDD33 | V _I = 0 to VDD33 | | | ±20 | μA |
| I _{OZP} | High-impedance, output current with internal pullup or pulldown resistor ⁽⁴⁾ | VDD33 | V _I = 0 to VDD33 | | | ±225 | μA |
| I _I | Input current ⁽⁵⁾ | VDD33 | V _I = 0 to VDD33 | | | ±15 | μA |

- (1) Applies to external inputs and bidirectional buffers
(2) Applies to external outputs and bidirectional buffers
(3) Applies to GRSTz
(4) Applies to pins with internal pullups/pulldowns
(5) Applies to external input buffers

5.6 Hub Input Supply Current

typical values measured at T_A = 25°C

| PARAMETER | VDD33 | VDD11 | UNIT |
|---|-------|-------|------|
| | 3.3V | 1.1V | |
| LOW-POWER MODES | | | |
| Power-on (after reset) | 5 | 39 | mA |
| Disconnect from host | 5 | 39 | mA |
| Suspend | 5 | 39 | mA |
| ACTIVE MODES (US STATE / DS STATE) | | | |
| 2.0 host / 1 HS device active | 48 | 71 | mA |
| 2.0 host / 2 HS devices active | 60 | 80 | mA |
| SMBUS Programming current | 79 | 225 | mA |

5.7 Power-Up Timing Requirements

| | | MIN | NOM | MAX | UNIT |
|-------------------|--|--------------------|-----|-----|---------|
| t_{d1} | VDD33 stable before VDD stable ⁽¹⁾ | see ⁽²⁾ | | | ms |
| t_{d2} | VDD and VDD33 stable before deassertion of GRSTz | 3 | | | ms |
| t_{su_io} | Setup for MISC inputs ⁽³⁾ sampled at the deassertion of GRSTz | 0.1 | | | μ s |
| t_{hd_io} | Hold for MISC inputs ⁽³⁾ sampled at the deassertion of GRSTz. | 0.1 | | | μ s |
| t_{VDD33_RAMP} | VDD33 supply ramp requirements | 0.2 | | 100 | ms |
| t_{VDD_RAMP} | VDD supply ramp requirements | 0.2 | | 100 | ms |

- (1) An active reset is required if the VDD33 supply is stable before the VDD11 supply. This active Reset shall meet the 3ms power-up delay counting from both power supplies being stable to the deassertion of GRSTz.
- (2) There is no power-on relationship between VDD33 and VDD unless GRSTz is only connected to a capacitor to GND. Then VDD must be stable minimum of 10 μ s before the VDD33.
- (3) MISC pins sampled at deassertion of GRSTz: FULLPWRMGMTz, GANGED, PWRCTL_POL, SMBUSz, BATEN[4:1], and AUTOENZ.

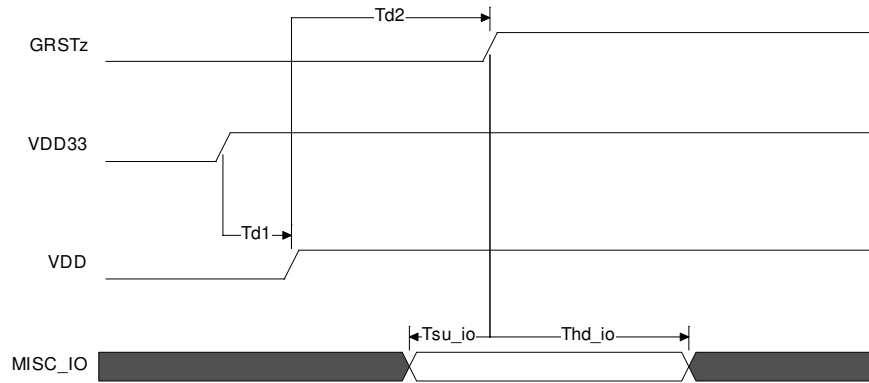


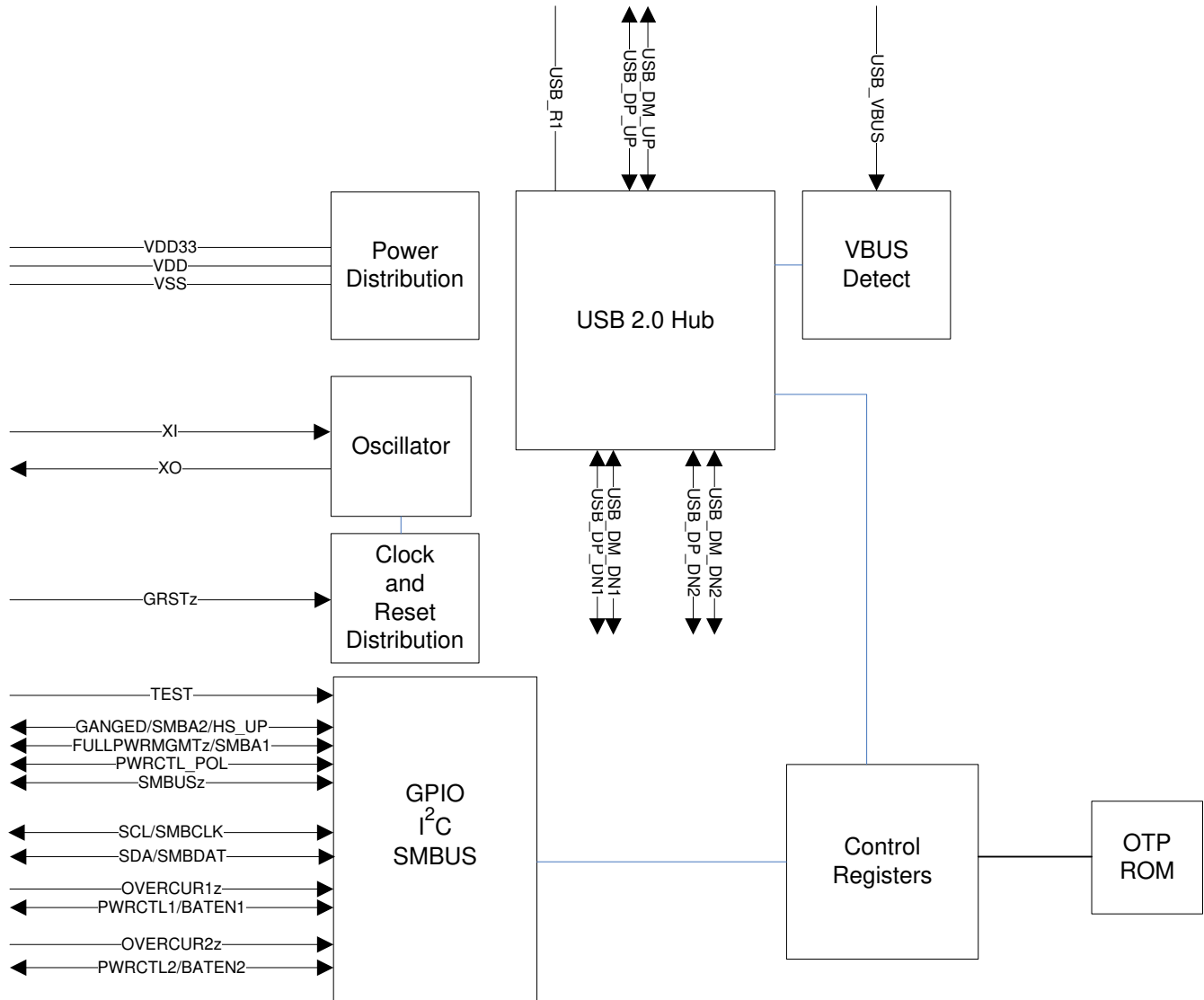
图 5-1. Power-Up Timing Requirements

6 Detailed Description

6.1 Overview

The TUSB4020BI is a two-port USB 2.0 hub, which provides USB high-speed/full-speed connections on the upstream port and USB high-speed, full-speed, or low-speed connections on the downstream ports. When the upstream port is connected to an electrical environment that supports high-speed and full-speed/low-speed connections, USB high-speed and full-speed/low-speed connectivity is enabled on the downstream ports. When the upstream port is connected to an electrical environment that only supports full-speed/low-speed connections, USB high-speed connectivity are disabled on the downstream ports.

6.2 Functional Block Diagram



6.3 Feature Description

6.3.1 Battery Charging Features

The TUSB4020BI provides support for battery charging. Battery charging support can be enabled on a per port basis through the REG_6h(batEn[1:0]).

Battery charging support includes both charging downstream port (CDP) and dedicated charging port (DCP) modes. The DCP mode is compliant with the Chinese Telecommunications Industry Standard YD/T 1591-2009.

In addition to standard DCP mode, the TUSB4020BI provides a mode (AUTOMODE) which automatically provides support for DCP devices and devices that support custom charging indication. AUTOMODE is disabled by default. When in AUTOMODE, the port automatically switches between a divider mode and the DCP mode depending on the portable device connected. The divider mode places a fixed DC voltage on the ports DP and DM signals which allows some devices to identify the capabilities of the charger. The default divider mode indicates support for up to 5 W. The divider mode can be configured to report a high-current setting (up to 10 W) through REG_Ah(HiCurAcPModeEn). When AUTOMODE is enabled through REG_Ah(autoModeEnz), the CDP mode is not functional. CDP mode can not be used when AUTOMODE is enabled.

The battery charging mode for each port depends on the state of Reg_6h(batEn[n]), the status of the VBUS input, and the state of REG_Ah(autoModeEnz) upstream port, as identified in 表 6-1. Battery charging can also be enabled through the PWRCTL1/BATEN1 and PWRCTL2/BATEN2 pins.

表 6-1. TUSB4020BI Battery Charging Modes

| batEn[n] | VBUS | autoModeEnz | BC Mode Port x (x = n + 1) |
|----------|-------------|-------------|--|
| 0 | Do not care | Do not care | Do not care |
| 1 | <4V | 0 | Automode ⁽³⁾ ⁽⁴⁾ |
| | | 1 | DCP ⁽¹⁾ ⁽²⁾ |
| | >4V | 1 | CDP ⁽¹⁾ |

- (1) USB device is USB Battery Charging Specification Revision 1.2 Compliant
- (2) USB device is Chinese Telecommunications Industry Standard YD/T 1591-2009
- (3) Auto-mode automatically selects divider-mode or DCP mode.
- (4) Divider mode can be configured for high-current mode through register or OTP settings.

6.3.2 USB Power Management

The TUSB4020BI can be configured for power switched applications using either per-port or ganged power-enable controls and overcurrent status inputs.

Power switch support is enabled by REG_5h(fullPwrMgmtz) and the per-port or ganged mode is configured by REG_5h(ganged). The power switch can also be enabled through the FULLPWRMGMTz pin. Also ganged or individual control can be controlled by the GANGED pin.

The TUSB4020BI supports both active-high and active-low power-enable controls. The PWRCTL[2:1] polarity is configured by REG_Ah(pwrctlPol). The polarity can also be configured by the PWRCTL_POL pin.

6.3.3 Clock Generation

The TUSB4020BI accepts a crystal input to drive an internal oscillator or an external clock source. Keep the XI and XO traces as short as possible and away from any switching leads to minimize noise coupling.

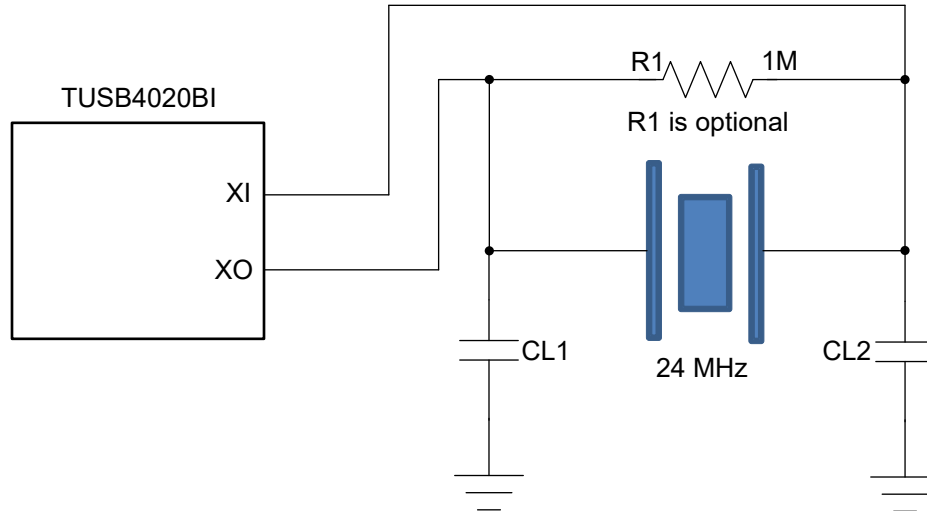


图 6-1. TUSB4020BI Clock

6.3.4 Power-Up and Reset

The TUSB4020BI does not have specific power sequencing requirements with respect to the VDD or VDD33 power rails. The VDD or VDD33 power rails can be powered up for an indefinite period of time while the other is not powered up if all of these constraints are met:

- All maximum ratings and recommended operating conditions are observed.
- All warnings about exposure to maximum rated and recommended conditions are observed, particularly junction temperature. These apply to power transitions as well as normal operation.
- Bus contention while VDD33 is powered-up must be limited to 100 hours over the projected lifetime of the device.
- Bus contention while VDD33 is powered-down can violate the absolute maximum ratings.

A supply bus is powered up when the voltage is within the recommended operating range. A supply bus is powered down when the supply is below that range, either stable or in transition.

A minimum reset duration of 3ms is required, which is defined as the time when the power supplies are in the recommended operating range to the deassertion of GRSTz. This can be generated using programmable-delay supervisory device or using an RC circuit.

6.4 Device Functional Modes

6.4.1 External Configuration Interface

The TUSB4020BI supports a serial interface for configuration register access. The device can be configured by an attached I²C EEPROM or accessed as a target by a SMBus-capable host controller. The external interface is enabled when both the SCL/SMBCLK and SDA/SMBDAT terminals are pulled up to 3.3V at the deassertion of reset. The mode, I²C controller, or SMBus target is determined by the state of SMBUSz terminal at reset.

6.5 Programming

6.5.1 One-Time Programmable (OTP) Configuration

The TUSB4020BI allows device configuration through OTP non-volatile memory (OTP). The programming of the OTP is supported using vendor-defined USB device requests. For details using the OTP features, contact a TI representative.

表 6-2 provides a list features which can be configured using the OTP. The bit field section in 表 6-2 shows which features can be controlled by OTP ROM. The bits not listed in the table are not accessible by the OTP ROM.

表 6-2. OTP Configurable Features

| CONFIGURATION REGISTER OFFSET | BIT FIELD | DESCRIPTION |
|-------------------------------|-----------|--|
| REG_01h | [7:0] | Vendor ID LSB |
| REG_02h | [7:0] | Vendor ID MSB |
| REG_03h | [7:0] | Product ID LSB |
| REG_04h | [7:0] | Product ID MSB |
| REG_07h | [0] | Port removable configuration for downstream ports 1. OTP configuration is inverse of rmb1[1:0], that is: 1 = Not removable 0 = Removable |
| REG_07h | [1] | Port removable configuration for downstream ports 2. OTP configuration is inverse of rmb2[1:0], that is: 1 = Not removable 0 = Removable |
| REG_0Ah | [1] | Automode enable |
| REG_0Ah | [4] | High-current divider mode enable. |
| REG_F2h | [3:1] | USB power switch power-on delay. |

6.5.2 I²C EEPROM Operation

The TUSB4020BI supports a single-controller, standard mode (100kbps) connection to a dedicated I²C EEPROM when the I²C interface mode is enabled. In I²C mode, the TUSB4020BI reads the contents of the EEPROM at bus address 1010000b using 7-bit addressing starting at address 0.

If the value of the EEPROM contents at byte 00h equals 55h, the TUSB4020BI loads the configuration registers according to the EEPROM map. If the first byte is not 55h, the TUSB4020BI exits the I²C mode and continues execution with the default values in the configuration registers. The hub does not connect on the upstream port until the configuration is completed. If the TUSB4020BI detects an unprogrammed EEPROM (value other than 55h), the device enters programming mode and a programming endpoint within the hub is enabled.

Note, the bytes located above offset Ah are optional. The requirement for data in those addresses depends on the options configured in the Device Configuration, Phy Custom Configuration, and Device Configuration 2 registers.

For details on I²C operation, refer to the UM10204 I²C-bus Specification and User Manual.

6.5.3 SMBus Target Operation

When the SMBus interface mode is enabled, the TUSB4020BI supports read block and write block protocols as a target-only SMBus device.

The TUSB4020BI target address is 1000 1xyz, where:

- x is the state of GANGED/SMBA2/HS_UP terminal at reset
- y is the state of FULLPWRMGMTz/SMBA1 terminal at reset
- z is the read/write bit; 1 = read access, 0 = write access.

If the TUSB4020BI is addressed by a host using an unsupported protocol, the device does not respond. The TUSB4020BI waits indefinitely for configuration by the SMBus host and does not connect on the upstream port until the SMBus host indicates configuration is complete by clearing the CFG_ACTIVE bit.

For details on SMBus requirements, refer to the System Management Bus Specification.

备注

During the SMBUS configuration the hub can draw an extra current, this extra current consumption ends as soon as the CFG_ACTIVE bit is cleared. For more information, see the [Hub Input Supply Current](#) section in this data sheet.

6.6 Register Maps

6.6.1 Configuration Registers

The internal configuration registers are accessed on byte boundaries. The configuration register values are loaded with defaults but can be overwritten when the TUSB4020BI is in I²C or SMBus mode.

表 6-3. TUSB4020BI Register Map

| BYTE ADDRESS | CONTENTS | EEPROM CONFIGURABLE |
|--------------|---|------------------------------|
| 00h | ROM Signature Register | No |
| 01h | Vendor ID LSB | Yes |
| 02h | Vendor ID MSB | Yes |
| 03h | Product ID LSB | Yes |
| 04h | Product ID MSB | Yes |
| 05h | Device Configuration Register | Yes |
| 06h | Battery Charging Support Register | Yes |
| 07h | Device Removable Configuration Register | Yes |
| 08h | Port Used Configuration Register | Yes |
| 09h | Reserved | Yes, program to 00h |
| 0Ah | Device Configuration Register 2 | Yes |
| 0Bh to 0Fh | Reserved | |
| 10h to 1Fh | UUID Byte [15:0] | No |
| 20h to 21h | LangID Byte [1:0] | Yes, if customStrings is set |
| 22h | Serial Number String Length | Yes, if customSerNum is set |
| 23h | Manufacturer String Length | Yes, if customStrings is set |
| 24h | Product String Length | Yes, if customStrings is set |
| 25h to 2Fh | Reserved | Yes |
| 30h to 4Fh | Serial Number String Byte [31:0] | Yes, if customSerNum is set |
| 50h to 8Fh | Manufacturer String Byte [63:0] | Yes, if customStrings is set |
| 90h to CFh | Product String Byte [63:0] | Yes, if customStrings is set |
| D0 to DFh | Reserved | No |
| F0h | Additional Feature Configuration Register | Yes |
| F1h | Reserved | Yes |
| F2h | Charging Port Control Register | Yes |
| F3 to F7h | Reserved | No |
| F8h | Device Status and Command Register | No |
| F9 to FFh | Reserved | No |

6.6.1.1 ROM Signature Register (offset = 0h) [reset = 0h]

图 6-2. Register Offset 0h

| | | | | | | | |
|-----|-----|-----|-----|-----|-----|-----|-----|
| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-4. ROM Signature Register

| Bit | Field | Type | Reset | Description |
|-----|--------------|------|-------|---|
| 7:0 | romSignature | R/W | 0h | ROM Signature Register. This register is used by the TUSB4020BI in I ² C mode to validate the attached EEPROM has been programmed. The first byte of the EEPROM is compared to the mask 55h and if not a match, the TUSB4020BI aborts the EEPROM load and executes with the register defaults. |

6.6.1.2 Vendor ID LSB Register (offset = 1h) [reset = 51h]

图 6-3. Register Offset 51h

| | | | | | | | |
|-----|-----|-----|-----|-----|-----|-----|-----|
| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| 0 | 1 | 0 | 1 | 0 | 0 | 0 | 1 |
| R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-5. Vendor ID LSB Register

| Bit | Field | Type | Reset | Description |
|-----|-------------|------|-------|--|
| 7:0 | vendorIdLsb | R/W | 51h | Vendor ID LSB. Least significant byte of the unique vendor ID assigned by the USB-IF; the default value of this register is 51h representing the LSB of the TI Vendor ID 0451h. The value can be overwritten to indicate a customer vendor ID. This field is read/write unless the OTP ROM VID and OTP ROM PID values are non-zero. If both values are non-zero, the value when reading this register shall reflect the OTP ROM value. |

6.6.1.3 Vendor ID MSB Register (offset = 2h) [reset = 4h]

图 6-4. Register Offset 2h

| | | | | | | | |
|-----|-----|-----|-----|-----|-----|-----|-----|
| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| 0 | 0 | 0 | 0 | 0 | 1 | 0 | 0 |
| R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-6. Vendor ID MSB Register

| Bit | Field | Type | Reset | Description |
|-----|-------------|------|-------|---|
| 7:0 | vendorIdMsb | R/W | 4h | Vendor ID MSB. Most significant byte of the unique vendor ID assigned by the USB-IF; the default value of this register is 04h representing the MSB of the TI Vendor ID 0451h. The value can be overwritten to indicate a customer vendor ID. This field is read/write unless the OTP ROM VID and OTP ROM PID values are non-zero. If both values are non-zero, the value when reading this register shall reflect the OTP ROM value. |

6.6.1.4 Product ID LSB Register (offset = 3h) [reset = 25h]

图 6-5. Register Offset 3h

| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----|-----|-----|-----|-----|-----|-----|-----|
| 0 | 0 | 1 | 0 | 0 | 1 | 0 | 1 |
| R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-7. Product ID LSB Register

| Bit | Field | Type | Reset | Description |
|-----|--------------|------|-------|--|
| 7:0 | productIdLsb | R/W | 25h | Product ID LSB. Least significant byte of the product ID assigned by TI. The default value of this register is 25h representing the LSB of the product ID assigned by TI. The value reported in the USB 2.0 device descriptor is the value of this register bit wise XORed with 00000010b. The value can be overwritten to indicate a customer product ID. This field is read/write unless the OTP ROM VID and OTP ROM PID values are non-zero. If both values are non-zero, the value when reading this register shall reflect the OTP ROM value. |

6.6.1.5 Product ID MSB Register (offset = 4h) [reset = 80h]

图 6-6. Register Offset 4h

| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----|-----|-----|-----|-----|-----|-----|-----|
| 1 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-8. Bit Descriptions - Product ID MSB Register

| Bit | Field | Type | Reset | Description |
|-----|--------------|------|-------|---|
| 7:0 | productIdLsb | R/W | 80h | Product ID MSB. Most significant byte of the product ID assigned by TI; the default value of this register is 80h representing the MSB of the product ID assigned by TI. The value can be overwritten to indicate a customer product ID. This field is read/write unless the OTP ROM VID and OTP ROM PID values are non-zero. If both values are non-zero, the value when reading this register reflects the OTP ROM value. |

6.6.1.6 Device Configuration Register (offset = 5h) [reset = 1Xh]

图 6-7. Register Offset 5h

| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----|-----|-----|---|-----|-----|-----|---|
| 0 | 0 | 0 | 1 | X | X | 0 | 0 |
| R/W | R/W | R/W | R | R/W | R/W | R/W | R |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-9. Device Configuration Register

| Bit | Field | Type | Reset | Description |
|-----|---------------|------|-------|---|
| 7 | customStrings | R/W | 1Xh | Custom strings enable. This bit controls the ability to write to the Manufacturer String Length, Manufacturer String, Product String Length, Product String, and Language ID registers. 0 = The Manufacturer String Length, Manufacturer String, Product String Length, Product String, and Language ID registers are read only. 1 = The Manufacturer String Length, Manufacturer String, Product String Length, Product String, and Language ID registers can be loaded by EEPROM or written by SMBus. The default value of this bit is 0. |
| 6 | customSernum | R/W | 1Xh | Custom serial number enable. This bit controls the ability to write to the serial number registers. 0 = The Serial Number String Length and Serial Number String registers are read only. 1 = The Serial Number String Length and Serial Number String registers can be loaded by EEPROM or written by SMBus. The default value of this bit is 0. |
| 5 | RSVD | R/W | 1Xh | Reserved. This bit is reserved. |
| 4 | RSVD | R | 1Xh | Reserved. This bit is reserved and returns 1 when read. |
| 3 | ganged | R/W | 1Xh | Ganged. This bit is loaded at the deassertion of reset with the value of the GANGED/SMBA2/HS_UP terminal. 0 = When fullPwrMgmtz = 0, each port is individually power switched and enabled by the PWRCTL[2:1]/BATEN[2:1] terminals 1 = When fullPwrMgmtz = 0, the power switch control for all ports is ganged and enabled by the PWRCTL1/BATEN1 terminal When the TUSB4020BI is in I ² C mode, the TUSB4020BI loads this bit from the contents of the EEPROM. When the TUSB4020BI is in SMBUS mode, the value can be overwritten by an SMBus host. |
| 2 | fullPwrMgmtz | R/W | 1Xh | Full Power Management. This bit is loaded at the deassertion of reset with the value of the FULLPWRMGMTz/SMBA1 terminal. 0 = Port power switching and over-current status reporting is enabled 1 = Port power switching and over-current status reporting is disabled When the TUSB4020BI is in I ² C mode, the TUSB4020BI loads this bit from the contents of the EEPROM. When the TUSB4020BI is in SMBUS mode, the value can be overwritten by an SMBus host. |
| 1 | RSVD | R/W | 1Xh | Reserved. This bit is reserved and must not be altered from the default. |
| 0 | RSVD | R | 1Xh | Reserved. This field is reserved and returns 0 when read. |

6.6.1.7 Battery Charging Support Register (offset = 6h) [reset = 0Xh]

图 6-8. Register Offset 6h

| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---|-----|-----|-----|-----|-----|-----|-----|
| 0 | 0 | 0 | 0 | 0 | 0 | X | X |
| R | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-10. Battery Charging Support Register

| Bit | Field | Type | Reset | Description |
|-----|------------|------|-------|--|
| 7:2 | RSVD | R | 0Xh | Reserved. Read only, returns 0 when read. |
| 1:0 | batEn[1:0] | R/W | 0Xh | Battery Charger Support. The bits in this field indicate whether the downstream port implements the charging port features. 0 = The port is not enabled for battery charging support features 1 = The port is enabled for battery charging support features Each bit corresponds directly to a downstream port, that is batEn0 corresponds to downstream port 1, and batEN1 corresponds to downstream port 2. The default value for these bits are loaded at the deassertion of reset with the value of PWRCTL/BATEN[1:0]. When in I2C/SMBus mode the bits in this field can be overwritten by EEPROM contents or by an SMBus host. |

6.6.1.8 Device Removable Configuration Register (offset = 7h) [reset = 0Xh]

图 6-9. Register Offset 7h

| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----|---|---|---|---|---|---|-----|
| 0 | 0 | 0 | 0 | 0 | 0 | X | X |
| R/W | R | R | R | R | R | R | R/W |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-11. Device Removable Configuration Register

| Bit | Field | Type | Reset | Description |
|-----|------------|------|-------|--|
| 7 | customRmbl | R/W | 0Xh | Custom removable status. When this field is a 1, the TUSB4020BI uses rmb1 bits in this register to identify removable status for the ports. |
| 6:2 | RSVD | R | 0Xh | Reserved. Read only, returns 0 when read. Bits 3:2 are RW. The bits are reserved and return 0 when read. |
| 1:0 | rmb1[1:0] | R/W | 0Xh | Removable. The bits in this field indicate whether a device attached to downstream ports 2 through 1 are removable or permanently attached. 0 = The device attached to the port is not removable 1 = The device attached to the port is removable Each bit corresponds directly to a downstream port n + 1, that is rmb10 corresponds to downstream port 1, rmb11 corresponds to downstream port 2, and so forth. This field is read only unless the customRmbl bit is set to 1. Otherwise the value of this field reflects the inverted values of the OTP ROM non_rmb[1:0] field. |

6.6.1.9 Port Used Configuration Register (offset = 8h) [reset = 0h]

图 6-10. Register Offset 8h

| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---|---|---|---|---|---|---|---|
| 0 | 0 | 0 | 0 | 0 | 0 | 1 | 1 |
| R | R | R | R | R | R | R | R |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-12. Port Used Configuration Register

| Bit | Field | Type | Reset | Description |
|-----|-------|------|-------|----------------------|
| 7:0 | RSVD | R | 0h | Reserved. Read only. |

6.6.1.10 PHY Custom Configuration Register (offset = 9h) [reset = 0h]

图 6-11. Register Offset 9h

| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---|---|-----|---|---|---|-----|-----|
| 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| R | R | R/W | R | R | R | R/W | R/W |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-13. PHY Custom Configuration Register

| Bit | Field | Type | Reset | Description |
|-----|-------|------|-------|--|
| 7:6 | RSVD | R | 0h | Reserved. Read only, returns 0 when read. |
| 5 | RSVD | R/W | 0h | Reserved. This bit is reserved and must not be altered from the default. |
| 4:2 | RSVD | R | 0h | Reserved. Read only, returns 0 when read. |
| 1:0 | RSVD | R/W | 0h | Reserved. This field is reserved and must not be altered from the default. |

6.6.1.11 Device Configuration Register 2 (offset = Ah)

图 6-12. Register Offset Ah

| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---|----|----|----|----|----|----|---|
| 0 | 0 | X | 0 | 0 | 0 | 0 | 0 |
| R | RW | RW | RW | RW | RW | RW | R |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-14. Bit Descriptions - Device Configuration Register 2

| Bit | Field Name | Access | Reset | Description |
|-----|------------------|--------|-------|---|
| 7 | RSVD | RO | | Reserved. Read only, returns 0 when read. |
| 6 | customBCfeatures | RW | | <p>Custom Battery Charging Feature Enable. This bit controls the ability to write to the battery charging feature configuration controls.</p> <p>0 = The HiCurAcqModeEn and AutoModeEnz bits are read only and the values are loaded from the OTP ROM.</p> <p>1 = The HiCurAcqModeEn and AutoModeEnz bits are read/write and can be loaded by EEPROM or written by SMBus. from this register.</p> <p>This bit can be written simultaneously with HiCurAcqModeEn and AutoModeEnz.</p> |
| 5 | pwrctlPol | RW | | <p>Power enable polarity. This bit is loaded at the deassertion of reset with the inverse value of the PWRCTL_POL terminal.</p> <p>0 = PWRCTL polarity is active low</p> <p>1 = PWRCTL polarity is active high</p> <p>When the TUSB4020BI is in I²C mode, the TUSB4020BI loads this bit from the contents of the EEPROM.</p> <p>When the TUSB4020BI is in SMBUS mode, the value can be overwritten by an SMBus host.</p> |
| 4 | HiCurAcqModeEn | RO/RW | | <p>High-current ACP mode enable. This bit enables the high-current tablet charging mode when the automatic battery charging mode is enabled for downstream ports.</p> <p>0 = High current divider mode disabled</p> <p>1 = High current divider mode enabled</p> <p>This bit is read only unless the customBCfeatures bit is set to 1. Otherwise the value of this bit reflects the value of the OTP ROM HiCurAcqModeEn bit.</p> |
| 3 | RSVD | RW | | Reserved |
| 2 | dsportEcrEn | RW | | <p>DSport ECR enable. This bit enables full implementation of the DSport ECR (April 2013).</p> <p>0 = DSport ECR (April 2013) is enabled with the exception of changes related to the CCS bit is set upon entering U0, and changes related to avoiding or reporting compliance mode entry.</p> <p>1 = The full DSport ECR (April 2013) is enabled.</p> |
| 1 | autoModeEnz | RO/RW | | <p>Automatic Mode Enable. This bit is loaded from the OTP ROM.</p> <p>The automatic mode only applies to downstream ports with battery charging enabled when the upstream port is not connected. Under these conditions:</p> <p>0 = Automatic mode battery charging features are enabled. Only battery charging DCP and custom BC (divider mode) is enabled.</p> <p>1 = Automatic mode is disabled; only battery charging DCP and CDP mode is supported.</p> <p>Note: when the upstream port is connected, battery charging CDP mode is supported on all ports when this field is one.</p> <p>This bit is read only unless the customBCfeatures bit is set to 1. Otherwise the value of this bit reflects the value of the OTP ROM AutoModeEnz bit.</p> |
| 0 | RSVD | RO | | Reserved. Read only, returns 0 when read. |

6.6.1.12 UUID Registers (offset = 10h to 1Fh)

图 6-13. Register Offset 10h to 1Fh

| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---|---|---|---|---|---|---|---|
| X | X | X | X | X | X | X | X |
| R | R | R | R | R | R | R | R |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-15. Bit Descriptions - UUID Byte N Register

| Bit | Field Name | Access | Reset | Description |
|-----|-------------|--------|-------|---|
| 7:0 | uuidByte[n] | RO | | UUID byte N. The UUID returned in the Container ID descriptor. The value of this register is provided by the device and is meets the UUID requirements of Internet Engineering Task Force (IETF) RFC 4122 A UUID URN Namespace. |

6.6.1.13 Language ID LSB Register (offset = 20h)

图 6-14. Register Offset 20h

| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----|-----|-----|-----|-----|-----|-----|-----|
| 0 | 0 | 0 | 0 | 1 | 0 | 0 | 1 |
| R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-16. Bit Descriptions - Language ID LSB Register

| Bit | Field Name | Access | Reset | Description |
|-----|------------|--------|-------|---|
| 7:0 | langIdLsb | RW | | Language ID least significant byte. This register contains the value returned in the LSB of the LANGID code in string index 0. The TUSB4020BI only supports one language ID. The default value of this register is 09h representing the LSB of the LangID 0409h indicating English United States. When customStrings is 1, this field can be overwritten by the contents of an attached EEPROM or by an SMBus host. |

6.6.1.14 Language ID MSB Register (offset = 21h)

图 6-15. Register Offset 21h

| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----|-----|-----|-----|-----|-----|-----|-----|
| 0 | 0 | 0 | 0 | 0 | 1 | 0 | 0 |
| R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-17. Bit Descriptions - Language ID MSB Register

| Bit | Field Name | Access | Reset | Description |
|-----|------------|--------|-------|--|
| 7:0 | langIdMsb | RO/RW | | Language ID most significant byte. This register contains the value returned in the MSB of the LANGID code in string index 0. The TUSB4020BI only supports one language ID. The default value of this register is 04h representing the MSB of the LangID 0409h indicating English United States. When customStrings is 1, this field can be overwritten by the contents of an attached EEPROM or by an SMBus host. |

6.6.1.15 Serial Number String Length Register (offset = 22h)

图 6-16. Register Offset 22h

| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----|-----|-----|-----|-----|-----|-----|-----|
| 0 | 0 | 0 | 1 | 1 | 0 | 0 | 0 |
| R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-18. Bit Descriptions - Serial Number String Length Register

| Bit | Field Name | Access | Reset | Description |
|-----|-----------------|--------|-------|--|
| 7:6 | RSVD | RO | | Reserved. Read only, returns 0 when read. |
| 5:0 | serNumStringLen | RO/RW | | Serial number string length. The string length in bytes for the serial number string. The default value is 18h indicating that a 24-byte serial number string is supported. The maximum string length is 32 bytes. When customSernum is 1, this field can be overwritten by the contents of an attached EEPROM or by an SMBus host. When the field is non-zero, a serial number string of serNumStringLen bytes is returned at string index 1 from the data contained in the Serial Number String registers. |

6.6.1.16 Manufacturer String Length Register (offset = 23h)

图 6-17. Register Offset 23h

| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---|-----|-----|-----|-----|-----|-----|-----|
| 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| R | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-19. Bit Descriptions - Manufacturer String Length Register

| Bit | Field Name | Access | Reset | Description |
|-----|--------------|--------|-------|---|
| 7 | RSVD | RO | | Reserved. Read only, returns 0 when read. |
| 6:0 | mfgStringLen | RO/RW | | Manufacturer string length. The string length in bytes for the manufacturer string. The default value is 0, indicating that a manufacturer string is not provided. The maximum string length is 64 bytes. When customStrings is 1, this field can be overwritten by the contents of an attached EEPROM or by an SMBus host. When the field is non-zero, a manufacturer string of mfgStringLen bytes is returned at string index 3 from the data contained in the Manufacturer String registers. |

6.6.1.17 Product String Length Register (offset = 24h)

图 6-18. Register Offset 24h

| | | | | | | | |
|---|-----|-----|-----|-----|-----|-----|-----|
| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| R | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-20. Bit Descriptions - Product String Length Register

| Bit | Field Name | Access | Reset | Description |
|-----|---------------|--------|-------|---|
| 7 | RSVD | RO | | Reserved. Read only, returns 0 when read. |
| 6:0 | prodStringLen | RO/RW | | Product string length. The string length in bytes for the product string. The default value is 0, indicating that a product string is not provided. The maximum string length is 64 bytes. When customStrings is 1, this field can be overwritten by the contents of an attached EEPROM or by an SMBus host. When the field is non-zero, a product string of prodStringLen bytes is returned at string index 2 from the data contained in the Product String registers. |

6.6.1.18 Serial Number Registers (offset = 30h to 4Fh)

图 6-19. Register Offset 30h to 4Fh

| | | | | | | | |
|-----|-----|-----|-----|-----|-----|-----|-----|
| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| X | X | x | x | x | x | x | x |
| R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-21. Bit Descriptions - Serial Number Registers

| Bit | Field Name | Access | Reset | Description |
|-----|-----------------|--------|-------|--|
| 7:0 | serialNumber[n] | RO/RW | | Serial Number byte N. The serial number returned in the Serial Number string descriptor at string index 1. The default value of these registers is set by TI. When customSernum is 1, these registers can be overwritten by EEPROM contents or by an SMBus host. |

6.6.1.19 Manufacturer String Registers (offset = 50h to 8Fh)

图 6-20. Register Offset 50h to 8Fh

| | | | | | | | |
|-----|-----|-----|-----|-----|-----|-----|-----|
| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-22. Bit Descriptions - Manufacturer String Registers

| Bit | Field Name | Access | Reset | Description |
|-----|------------------|--------|-------|--|
| 7:0 | mfgStringByte[n] | RO/RW | | Manufacturer string byte N. These registers provide the string values returned for string index 3 when mfgStringLen is greater than 0. The number of bytes returned in the string is equal to mfgStringLen. The programmed data should be in UNICODE UTF-16LE encodings as defined by The Unicode Standard, Worldwide Character Encoding, Version 5.0. |

6.6.1.20 Product String Registers (offset = 90h to CFh)

图 6-21. Register Offset 90h to CFh

| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----|-----|-----|-----|-----|-----|-----|-----|
| 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-23. Bit Descriptions - Product String Byte N Register

| Bit | Field Name | Access | Reset | Description |
|-----|-------------------|--------|-------|---|
| 7:0 | prodStringByte[n] | RW | | Product string byte N. These registers provide the string values returned for string index 2 when prodStringLen is greater than 0. The number of bytes returned in the string is equal to prodStringLen. The programmed data should be in UNICODE UTF-16LE encodings as defined by The Unicode Standard, Worldwide Character Encoding, Version 5.0. |

6.6.1.21 Additional Feature Configuration Register (offset = F0h)

图 6-22. Register Offset F0h

| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---|-----|-----|-----|-----|-----|-----|-----|
| 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| R | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-24. Bit Descriptions - Additional Feature Configuration Register

| Bit | Field Name | Access | Reset | Description |
|-----|------------|--------|-------|---|
| 7:1 | RSVD | RO | | Reserved. Read only, returns 0 when read. |
| 0 | RSVD | RW | | Reserved This bit is loaded at the deassertion of reset with the value of the SCL/SMBCLK terminal. |

6.6.1.22 Charging Port Control Register (offset = F2h)

图 6-23. Register Offset F2h

| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---|---|---|---|-----|-----|-----|-----|
| 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| R | R | R | R | R/W | R/W | R/W | R/W |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-25. Bit Descriptions - Charging Port Control Register

| Bit | Field Name | Access | Reset | Description |
|-----|------------|--------|-------|--|
| 7:4 | RSVD | RO | | Reserved. Read only, returns 0 when read. |
| 3:1 | pwrOnTime | RW | | Power-On Delay Time. When dsportEcrEn is set, this field sets the delay time from the removal disable of PWRCTL to the enable of PWRCTL when transitioning battery charging modes. For example, when disabling the power on a transition from custom charging mode to Dedicated Charging Port Mode. The nominal timing is defined as follows: $TPWRON_EN = (pwrOnTime + 1) \times 200ms \quad (1)$ These registers can be overwritten by EEPROM contents or by an SMBus host. |
| 0 | RSVD | RW | | Reserved. This bit is reserved and must not be altered from the default. |

6.6.1.23 Device Status and Command Register (offset = F8h)

图 6-24. Register Offset F8h

| | | | | | | | |
|---|---|---|---|---|---|-----|-----|
| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| R | R | R | R | R | R | RSU | RCU |

LEGEND: R/W = Read/Write; R = Read only; - n = value after reset

表 6-26. Bit Descriptions - Device Status and Command Register

| Bit | Field Name | Access | Reset | Description |
|-----|------------|--------|-------|---|
| 7:2 | RSVD | R | | Reserved. Read only, returns 0 when read. |
| 1 | smbusRst | RSU | | SMBus interface reset. This bit loads the registers back to the GRSTz values. This bit is set by writing a 1 and is cleared by hardware on completion of the reset. A write of 0 has no effect. |
| 0 | cfgActive | RCU | | Configuration active. This bit indicates that configuration of the TUSB4020BI is currently active. The bit is set by hardware when the device enters the I ² C or SMBus mode. The TUSB4020BI does not connect on the upstream port while this bit is 1. When in the SMBus mode, this bit must be cleared by the SMBus host to exit the configuration mode and allow the upstream port to connect. The bit is cleared by a writing 1. A write of 0 has no effect. |

7 Application and Implementation

备注

以下应用部分中的信息不属于 TI 器件规格的范围，TI 不担保其准确性和完整性。TI 的客户应负责确定器件是否适用于其应用。客户应验证并测试其设计，以确保系统功能。

7.1 Application Information

The TUSB4020BI is a two-port USB 2.0 hub, which provides USB high-speed/full-speed connections on the upstream port and USB high-speed, full-speed, or low-speed connections on the downstream port. The TUSB4020BI can be used in any application that needs additional USB compliant ports. For example, a specific notebook can only have two downstream USB ports. By using the TUSB4020BI, the notebook can increase the downstream port count to three.

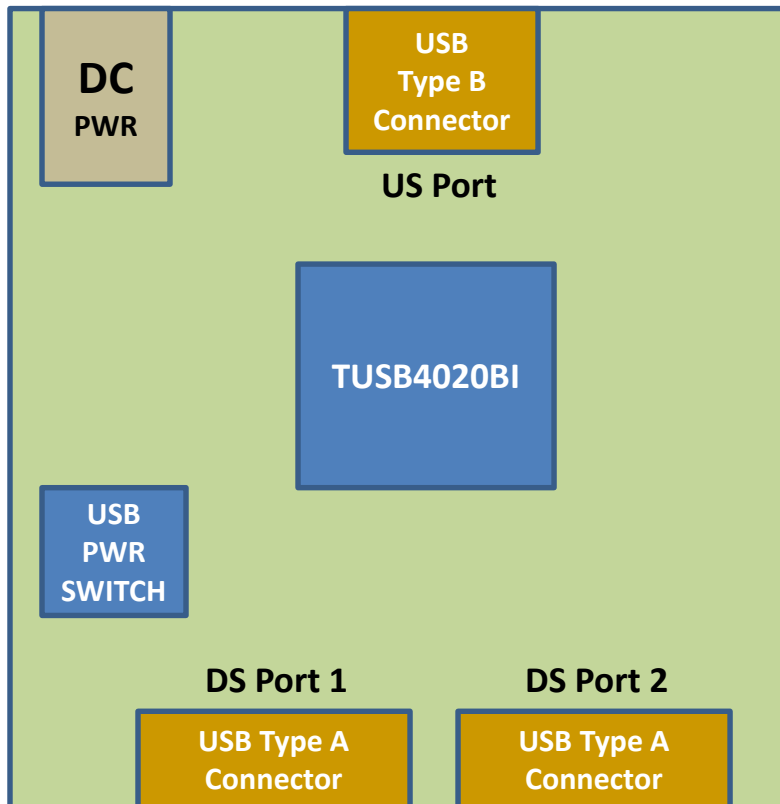


图 7-1. Discrete USB Hub Product

7.1.1 Crystal Requirements

The crystal must be fundamental mode with load capacitance of 12pF to 24pF and frequency stability rating of ± 100 PPM or better. To ensure proper start-up oscillation condition, TI recommends a maximum crystal equivalent series resistance (ESR) of $50\ \Omega$. Use a parallel load capacitor if a crystal source is used. The exact load capacitance value used depends on the crystal vendor. Refer to application note [Selection and Specification of Crystals for Texas Instruments USB 2.0 Devices](#) for details on how to determine the load capacitance value.

7.1.2 Input Clock Requirements

When using an external clock source such as an oscillator, make sure the reference clock has a ± 100 PPM or better frequency stability and has less than 50ps absolute peak-to-peak jitter. Tie XI to the 1.8V clock source and leave the XO pin floating.

7.2 Typical Applications

A common application for the TUSB4020BI is as a self-powered standalone USB hub product. The product is powered by an external 5V DC power adapter. In this application using a USB cable, TUSB4020BI device's upstream port is plugged into a USB host controller. The downstream ports of the TUSB4020BI are exposed to users for connecting USB hard drives, camera, flash drive, and so forth.

7.2.1 Upstream Port Implementation

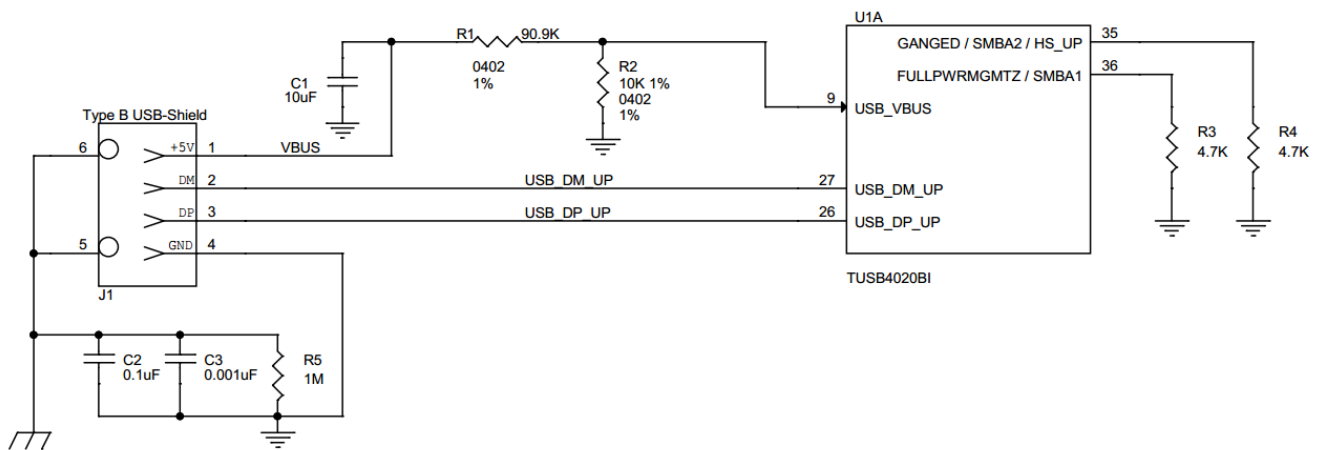


图 7-2. Upstream Port Implementation Schematic

7.2.1.1 Design Requirements

表 7-1. Input Parameters

| DESIGN PARAMETER | EXAMPLE VALUE |
|--|------------------------------|
| VDD supply | 1.1V |
| VDD33 supply | 3.3V |
| Upstream port USB support (HS, FS) | HS, FS |
| Downstream port 1 USB support (HS, FS, LS) | HS, FS, LS |
| Downstream port 2 USB support (HS, FS, LS) | HS, FS, LS |
| Number of removable downstream ports | 2 |
| Number of non-removable downstream ports | 0 |
| Full power management of downstream ports | Yes (FULLPWRMGMTZ = 0) |
| Individual control of downstream port power switch | Yes (GANGED = 0) |
| Power switch enable polarity | Active high (PWRCTL_POL = 0) |
| Battery charge support for downstream port 1 | Yes |
| Battery charge support for downstream port 2 | Yes |
| I ² C EEPROM support | No |
| 24MHz clock source | Crystal |

7.2.1.2 Detailed Design Procedure

The upstream of the TUSB4020BI is connected to a USB2 type B connector. This particular example has GANGED terminal and FULLPWRTMGMTZ terminal pulled low, which results in individual power support each downstream port. The VBUS signal from the USB2 type B connector is fed through a voltage divider. The purpose of the voltage divider is to make sure the level meets USB_VBUS input requirements.

7.2.1.3 Application Curves

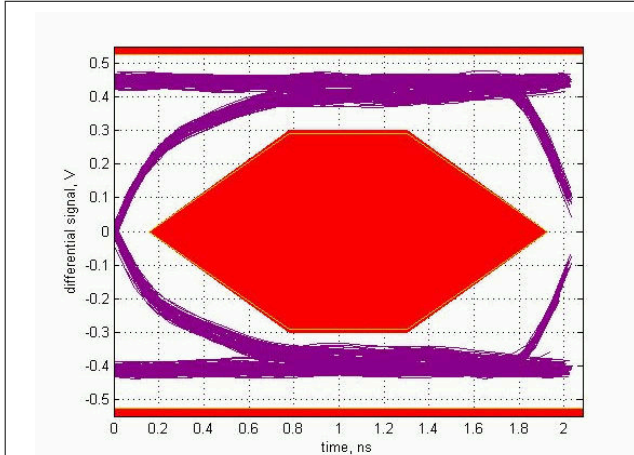


图 7-3. HighSpeed TX Eye for Downstream Port 1

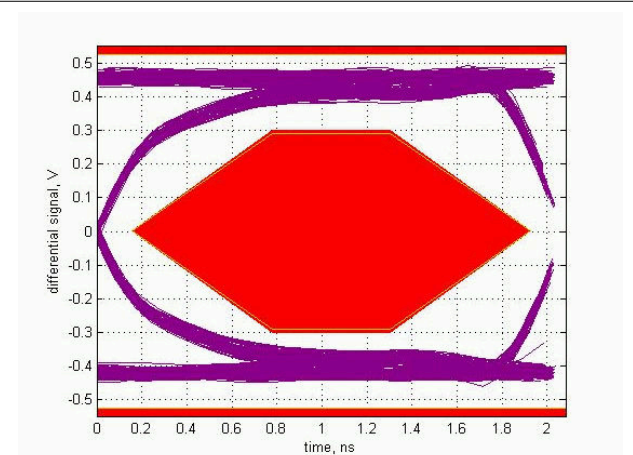


图 7-4. HighSpeed TX Eye for Downstream Port 2

7.2.2 Downstream Port 1 Implementation

The downstream port 1 of the TUSB4020BI is connected to a USB2 type A connector. With BATEN1 terminal pulled up, battery charge support is enabled for port 1. If battery charge support is not needed, then uninstall the pullup resistor on BATEN1. The PWRCTL_POL is pulled-down, which results in active-high power enable (PWRCTL1 and PWRCTL2) for a USB VBUS power switch.

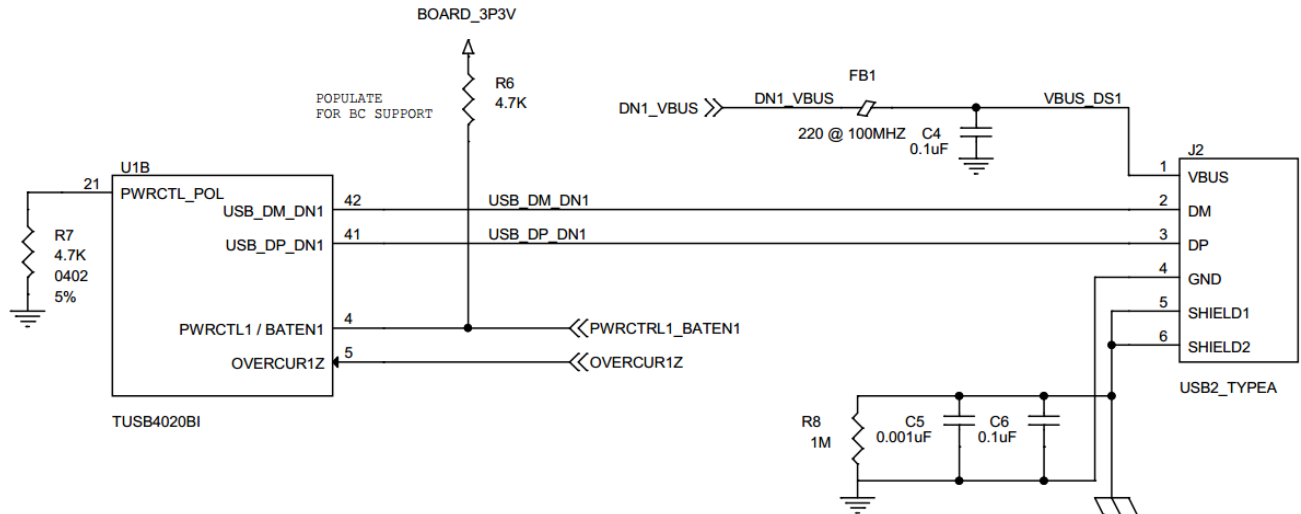


图 7-5. Downstream Port 1 Implementation Schematic

7.2.3 Downstream Port 2 Implementation

The downstream port 2 of the TUSB4020BI is connected to a USB2 type A connector. With BATEN2 terminal pulled up, battery charge support is enabled for port 2. If battery charge support is not needed, then uninstall the pullup resistor on BATEN2.

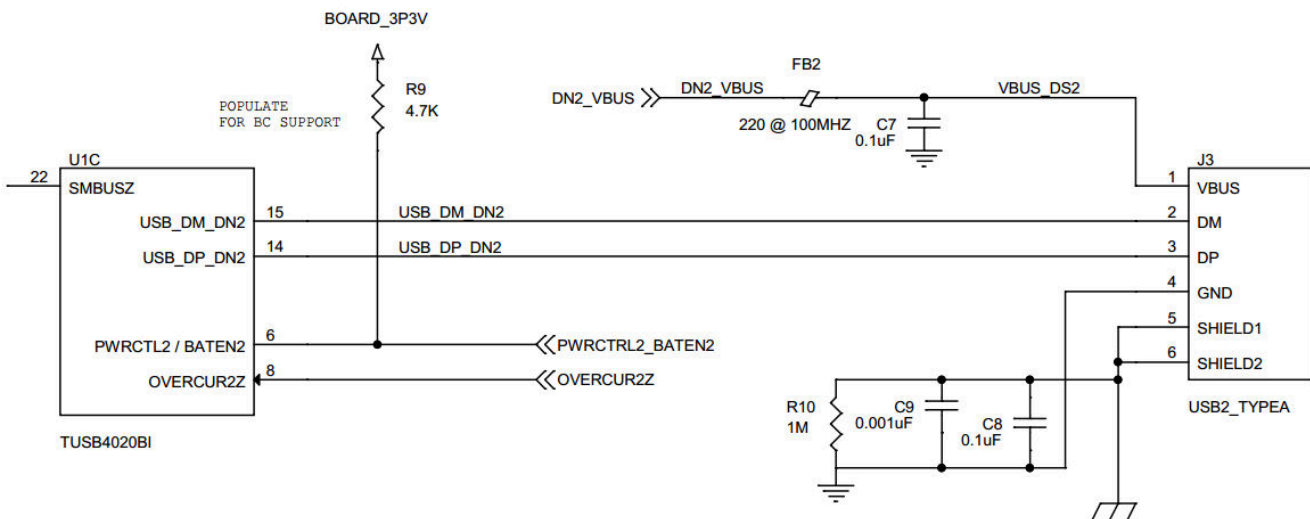


图 7-6. Downstream Port 2 Implementation Schematic

7.2.4 VBUS Power Switch Implementation

This particular example uses the TI [TPS2561](#) dual-channel precision adjustable current-limited power switch. For details on this power switch or other power switches available from TI, refer to [www.ti.com](#).

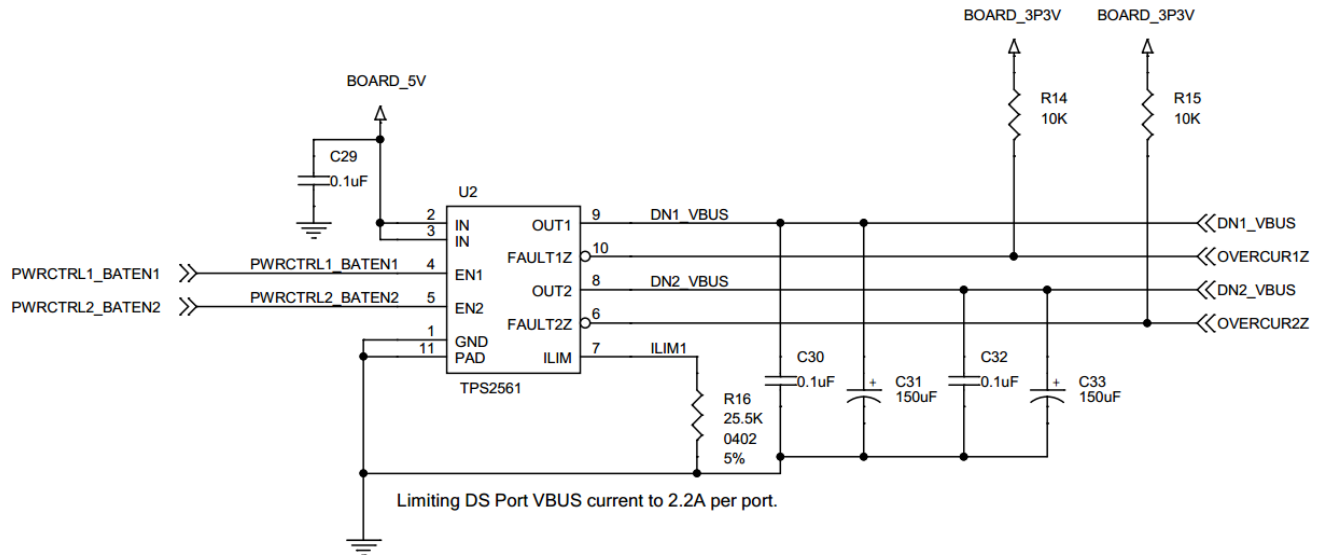


图 7-7. Power Switch Implementation Schematic

7.2.5 Clock, Reset, and Miscellaneous

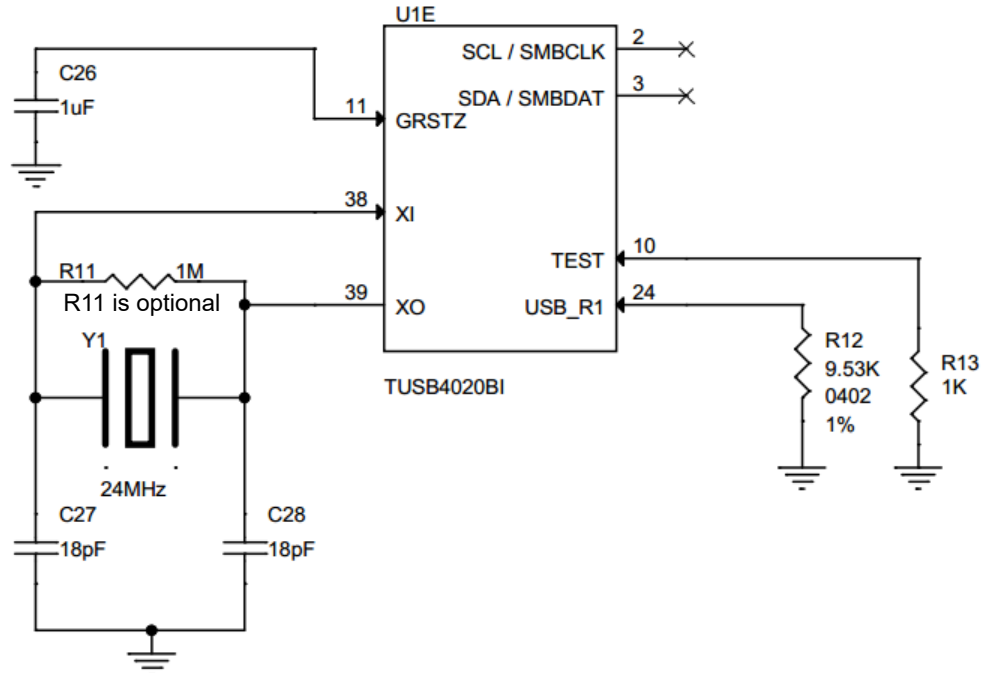


图 7-8. Clock, Reset, and Miscellaneous Schematic

7.2.6 Power Implementation

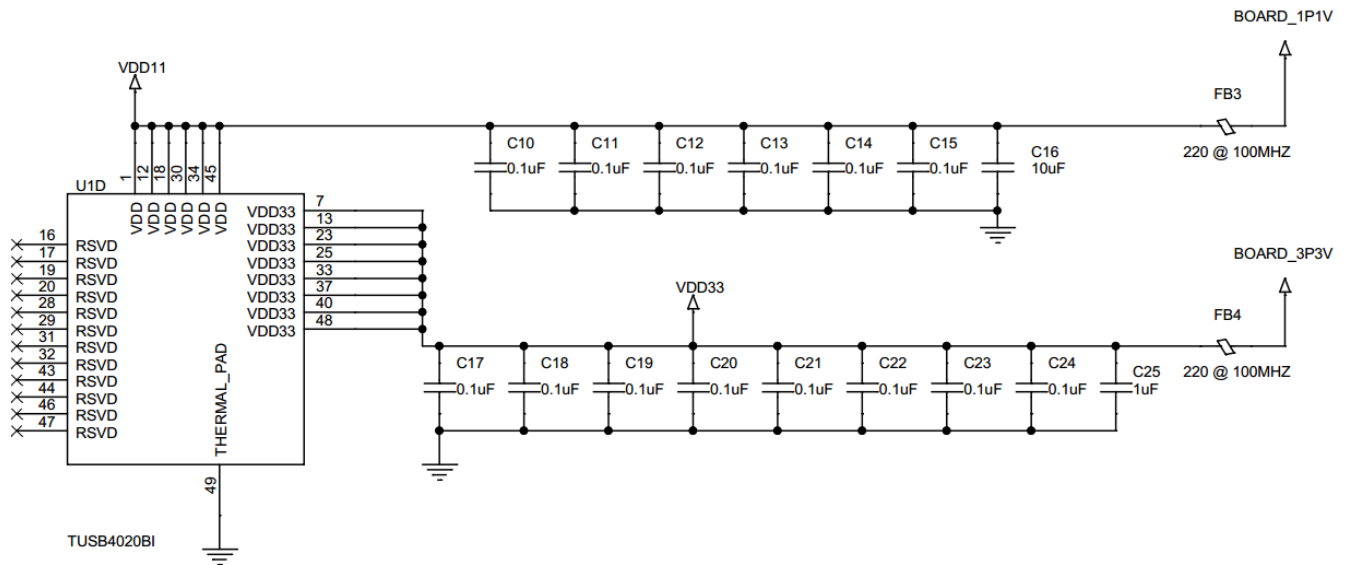


图 7-9. Power Implementation Schematic

7.3 Power Supply Recommendations

7.3.1 Power Supply

Implement V_{DD} and V_{DD33} as a single power plane.

- The V_{DD} terminals of the TUSB4020BI supply 1.1V (nominal) power to the core of the TUSB4020BI. This power rail can be isolated from all other power rails by a ferrite bead to reduce noise.
- The DC resistance of the ferrite bead on the core power rail can affect the voltage provided to the device due to the high current draw on the power rail. The output of the core voltage regulator can need to be adjusted to account for this or a ferrite bead with low DC resistance (less than 0.05Ω) can be selected.
- The V_{DD33} terminals of the TUSB4020BI supply 3.3V power rail to the I/O of the TUSB4020BI. This power rail can be isolated from all other power rails by a ferrite bead to reduce noise.
- All power rails require a $10\mu\text{F}$ capacitor or $1\mu\text{F}$ capacitors for stability and noise immunity. These bulk capacitors can be placed anywhere on the power rail. Place the smaller decoupling capacitors as close to the TUSB4020BI power pins as possible with an optimal grouping of two of differing values per pin.

7.3.2 Downstream Port Power

- The downstream port power, VBUS, must be supplied by a source capable of supplying 5V and at least 500mA per port. Downstream port power switches can be controlled by the TUSB4020BI signals. It is possible to leave the downstream port power always enabled.
- Each downstream port's VBUS requires a large bulk low-ESR capacitor of $22\mu\text{F}$ or larger to limit in-rush current.
- TI recommends ferrite beads on the VBUS pins of the downstream USB port connections for both ESD and EMI reasons. A $0.1\mu\text{F}$ capacitor on the USB connector side of the ferrite provides a low-impedance path to ground for fast rise time ESD current that might have coupled onto the VBUS trace from the cable.

7.3.3 Ground

TI recommends to use only one board ground plane in the design. This provides the best image plane for signal traces running above the plane. Connect the thermal pad of the TUSB4020BI and any of the voltage regulators to this plane with vias. An earth or chassis ground is only implemented near the USB port connectors on a different plane for EMI and ESD purposes.

7.4 Layout

7.4.1 Layout Guidelines

7.4.1.1 Placement

1. Place a $9.53k\ \Omega \pm 1\%$ resistor connected to terminal USB_R1 as close as possible to the TUSB4020BI.
2. Place a $0.1\ \mu\text{F}$ capacitor as close as possible on each V_{DD} and V_{DD33} power pin.
3. Place the ESD and EMI protection devices (if used) as close as possible to the USB connector.
4. If a crystal is used, place the crystal as close as possible to the TUSB4020BI device's XI and XO terminals.
5. Place voltage regulators as far away as possible from the TUSB4020BI, crystal, and differential pairs.
6. In general, place the large bulk capacitors associated with each power as close as possible to the voltage regulators.

7.4.1.2 Package Specific

1. The TUSB4020BI package has a 0.5mm pin pitch.
2. The TUSB4020BI package has a $3.6\text{mm} \times 3.6\text{mm}$ thermal pad. This thermal pad must be connected to ground through a system of vias.
3. Make sure that all vias under the device, except for those connected to thermal pad, are solder masked to avoid potential issues with thermal pad layouts.

7.4.1.3 Differential Pairs

This section describes the layout recommendations for all of the TUSB4020BI differential pairs: USB_DP_XX, USB_DM_XX.

- Must be designed with a differential impedance of $90\ \Omega \pm 10\%$.
- To minimize crosstalk, TI recommends to keep high-speed signals away from each other. Separate each pair by at least $5\times$ the signal trace width. Separating with ground as depicted in the layout example also helps minimize crosstalk.
- Route all differential pairs on the same layer adjacent to a solid ground plane.
- Do not route differential pairs over any plane split.
- Adding test points causes impedance discontinuity, and therefore, negatively impacts signal performance. If test points are used, place the test points in series and symmetrically. The test points must not be placed in a manner that causes stub on the differential pair.
- Avoid 90° turns in trace. Keep the use of bends in differential traces to a minimum. When bends are used, make sure the number of left and right bends are as equal as possible and that the angle of the bend is $\geq 135^\circ$. Take this action to minimize any length mismatch caused by the bends, and therefore, minimize the impact bends have on EMI.
- Minimize the trace lengths of the differential pair traces. Eight inches is the maximum recommended trace length for USB 2.0 differential-pair signals. Longer trace lengths require very careful routing to assure proper signal integrity.
- Match the etch lengths of the differential pair traces (that is DP and DM). Make sure the USB 2.0 differential pairs do not exceed 50mil relative trace length difference.
- Minimize the use of vias in the differential-pair paths as much as possible. If this is not practical, ensure that the same via type and placement are used for both signals in a pair. Place any vias used as close as possible to the TUSB4020BI device.
- Do not place power fuses across the differential-pair traces.

7.4.2 Layout Example

图 7-10 显示了一个连接到 USB3 Type B 连接器的上游端口的布局示例。连接到 USB2 Type B 连接器的布局是类似的。

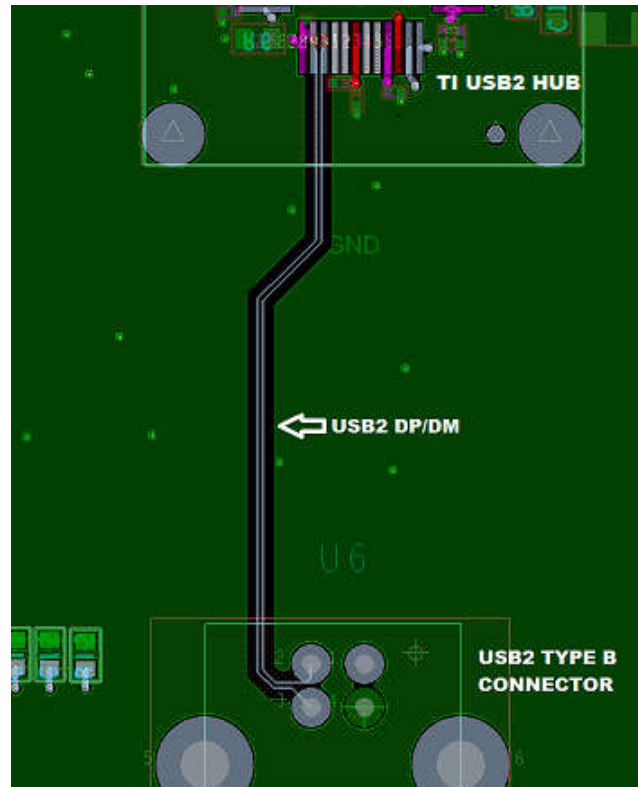


图 7-10. Upstream Port

图 7-11 shows an example layout of the Downstream Port to a USB3 Type A connector. The routing to a USB2 Type A connector is similar.

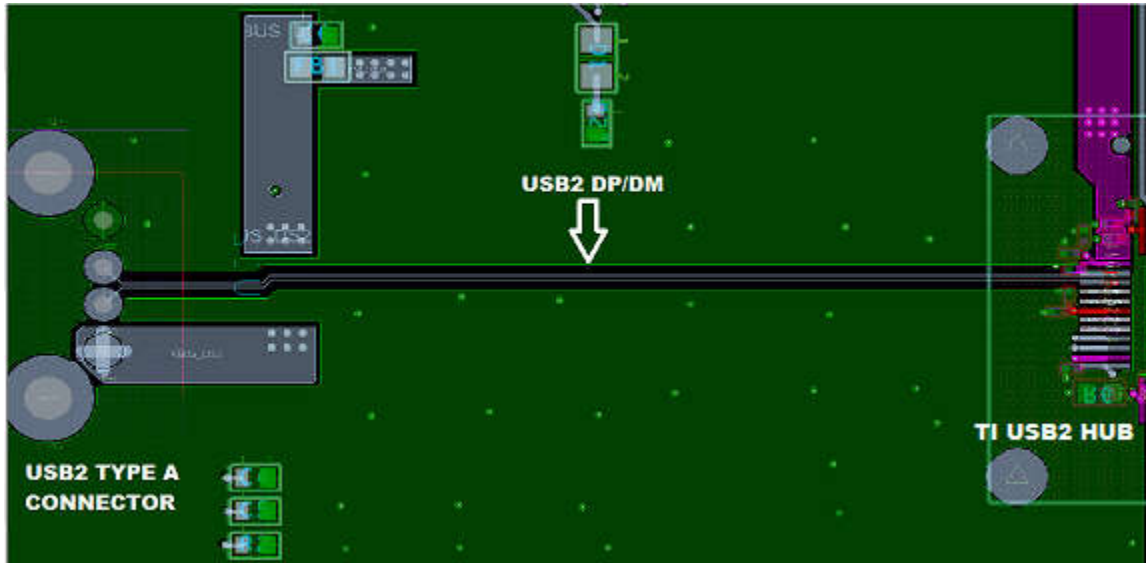


图 7-11. Downstream Port

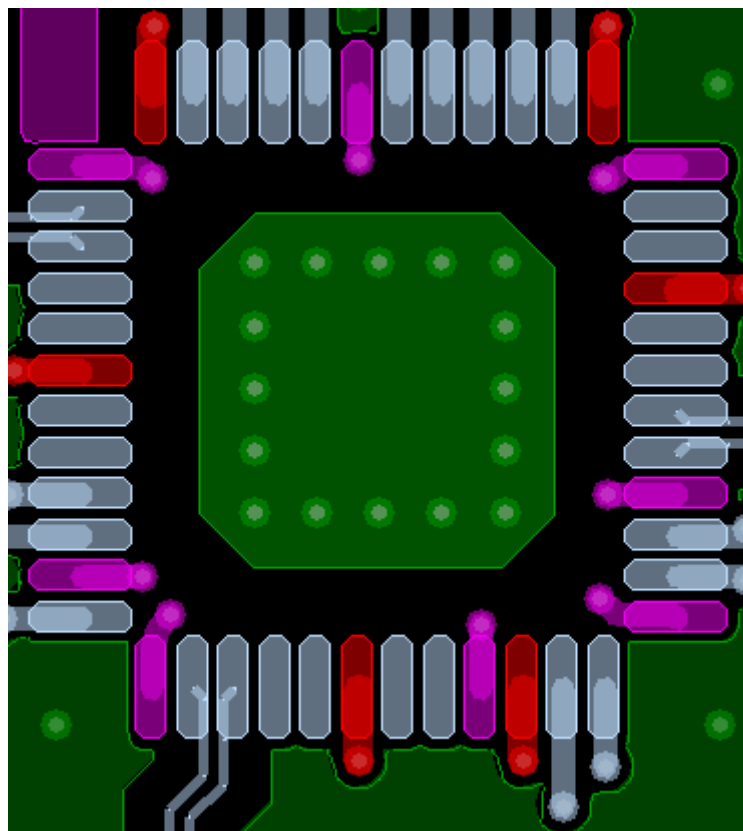


图 7-12. Thermal Pad

8 Device and Documentation Support

8.1 Documentation Support

8.1.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, [Selection and Specification of Crystals for Texas Instruments USB 2.0 Devices application note](#)
- Texas Instruments, [TPS256x Dual Channel Precision Adjustable Current-limited Power Switches data sheet](#)

8.2 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击 [通知](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

8.3 支持资源

[TI E2E™ 中文支持论坛](#) 是工程师的重要参考资料，可直接从专家处获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题，获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的 [使用条款](#)。

8.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

所有商标均为其各自所有者的财产。

8.5 静电放电警告



静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

8.6 术语表

[TI 术语表](#) 本术语表列出并解释了术语、首字母缩略词和定义。

9 Revision History

注：以前版本的页码可能与当前版本的页码不同

| Changes from Revision D (January 2022) to Revision E (July 2024) | Page |
|--|------|
| • 更新了数据表以包含丰富的术语..... | 1 |
| • Added the XO pin to the <i>Absolute Maximum Ratings</i> voltage parameters..... | 7 |
| • Changed the minimum voltage for the XI pin from: - 0.3V to: - 0.4V..... | 7 |
| • Added maximum junction temperature to the <i>Absolute Maximum Ratings</i> table..... | 7 |
| • Added the XI, XO voltage to the <i>Recommended Operating Conditions</i> table | 7 |

| Changes from Revision C (April 2018) to Revision D (January 2022) | Page |
|---|------|
| • 更新了整个文档中的表格、图和交叉参考的编号格式..... | 1 |
| • 删除了第 4 页、第 11 页、第 12 页和第 31 页上的晶体 <i>1M 反馈电阻器</i> 要求..... | 1 |
| • Updated the pin description from: <i>SMBus target address bits 2 and 3 are always 1 for TUSB4020BI</i> to: <i>SMBus target address bit 3 is always 1 for TUSB4020BI</i> | 4 |
| • Corrected the default register setting for the <i>Register offset 9h</i> | 19 |

- Updated the *Clock, Reset, and Miscellaneous Schematic* in the *Clock, Reset, and Miscellaneous* section....[30](#)
-

Changes from Revision B (June 2017) to Revision C (April 2018) Page

- Changed the *Absolute Maximum Ratings* table, added pin voltages..... [7](#)
-

Changes from Revision A (March 2016) to Revision B (June 2017) Page

- Added SMBUS Programming current to the *Hub Input Supply Current* table [8](#)
 - Added Note to the *SMBus Target Operation* section..... [13](#)
-

Changes from Revision * (July 2015) to Revision A (March 2016) Page

- 删除了 [节 1](#) “DM/DP 极性交换” [1](#)
-

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|-------------------------|
| TUSB4020BIPHP | ACTIVE | HTQFP | PHP | 48 | 250 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | T4020BI | Samples |
| TUSB4020BIPHPG4 | ACTIVE | HTQFP | PHP | 48 | 250 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | T4020BI | Samples |
| TUSB4020BIPHPR | ACTIVE | HTQFP | PHP | 48 | 1000 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | T4020BI | Samples |
| TUSB4020BIPHPRG4 | ACTIVE | HTQFP | PHP | 48 | 1000 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | T4020BI | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and

continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TUSB4020BI :

- Automotive : [TUSB4020BI-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

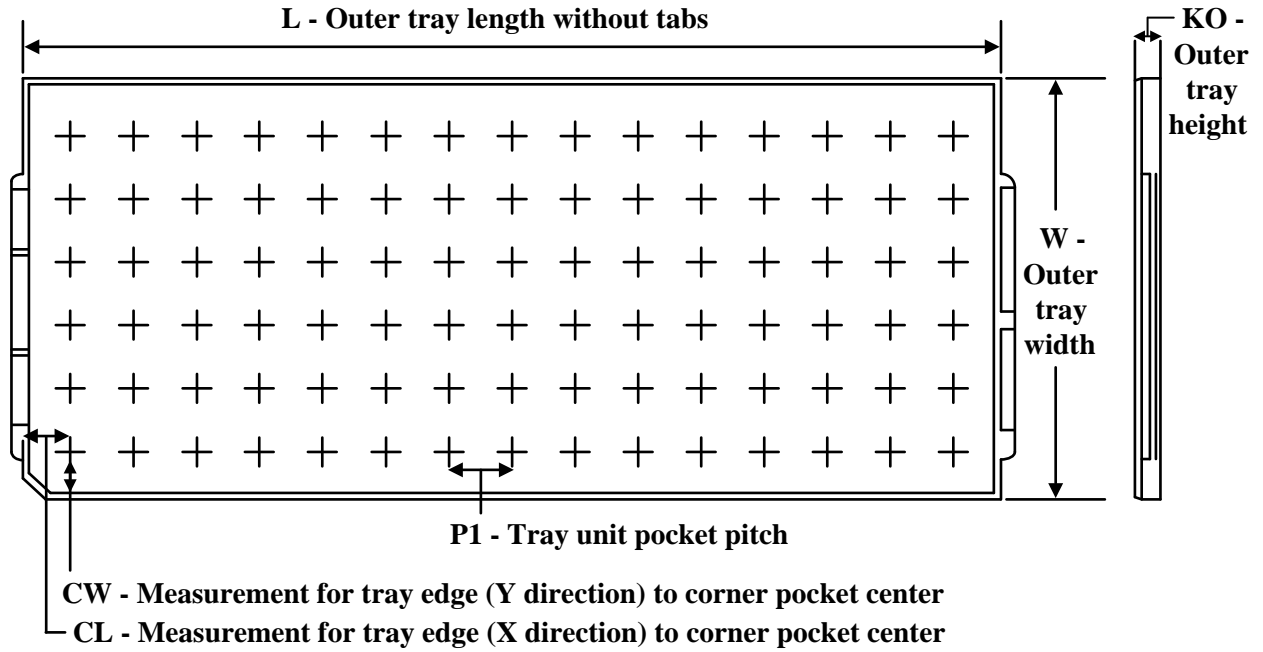

*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TUSB4020BIPHPR | HTQFP | PHP | 48 | 1000 | 330.0 | 16.4 | 9.6 | 9.6 | 1.5 | 12.0 | 16.0 | Q2 |
| TUSB4020BIPHPRG4 | HTQFP | PHP | 48 | 1000 | 330.0 | 16.4 | 9.6 | 9.6 | 1.5 | 12.0 | 16.0 | Q2 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TUSB4020BIPHPR | HTQFP | PHP | 48 | 1000 | 336.6 | 336.6 | 31.8 |
| TUSB4020BIPHPRG4 | HTQFP | PHP | 48 | 1000 | 336.6 | 336.6 | 31.8 |

TRAY


Chamfer on Tray corner indicates Pin 1 orientation of packed units.

*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | Unit array matrix | Max temperature (°C) | L (mm) | W (mm) | K0 (µm) | P1 (mm) | CL (mm) | CW (mm) |
|-----------------|--------------|--------------|------|-----|-------------------|----------------------|--------|--------|---------|---------|---------|---------|
| TUSB4020BIPHP | PHP | HTQFP | 48 | 250 | 10 x 25 | 150 | 315 | 135.9 | 7620 | 12.2 | 11.1 | 11.25 |
| TUSB4020BIPHPG4 | PHP | HTQFP | 48 | 250 | 10 x 25 | 150 | 315 | 135.9 | 7620 | 12.2 | 11.1 | 11.25 |

GENERIC PACKAGE VIEW

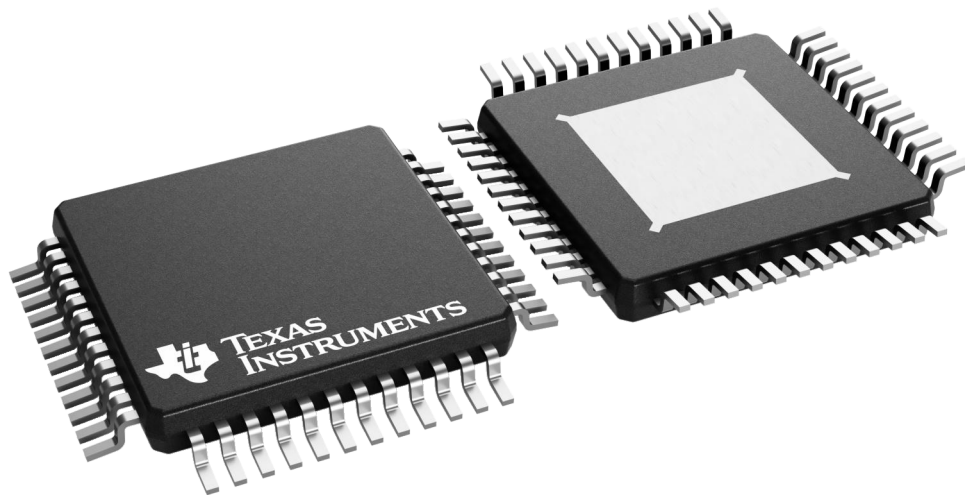
PHP 48

TQFP - 1.2 mm max height

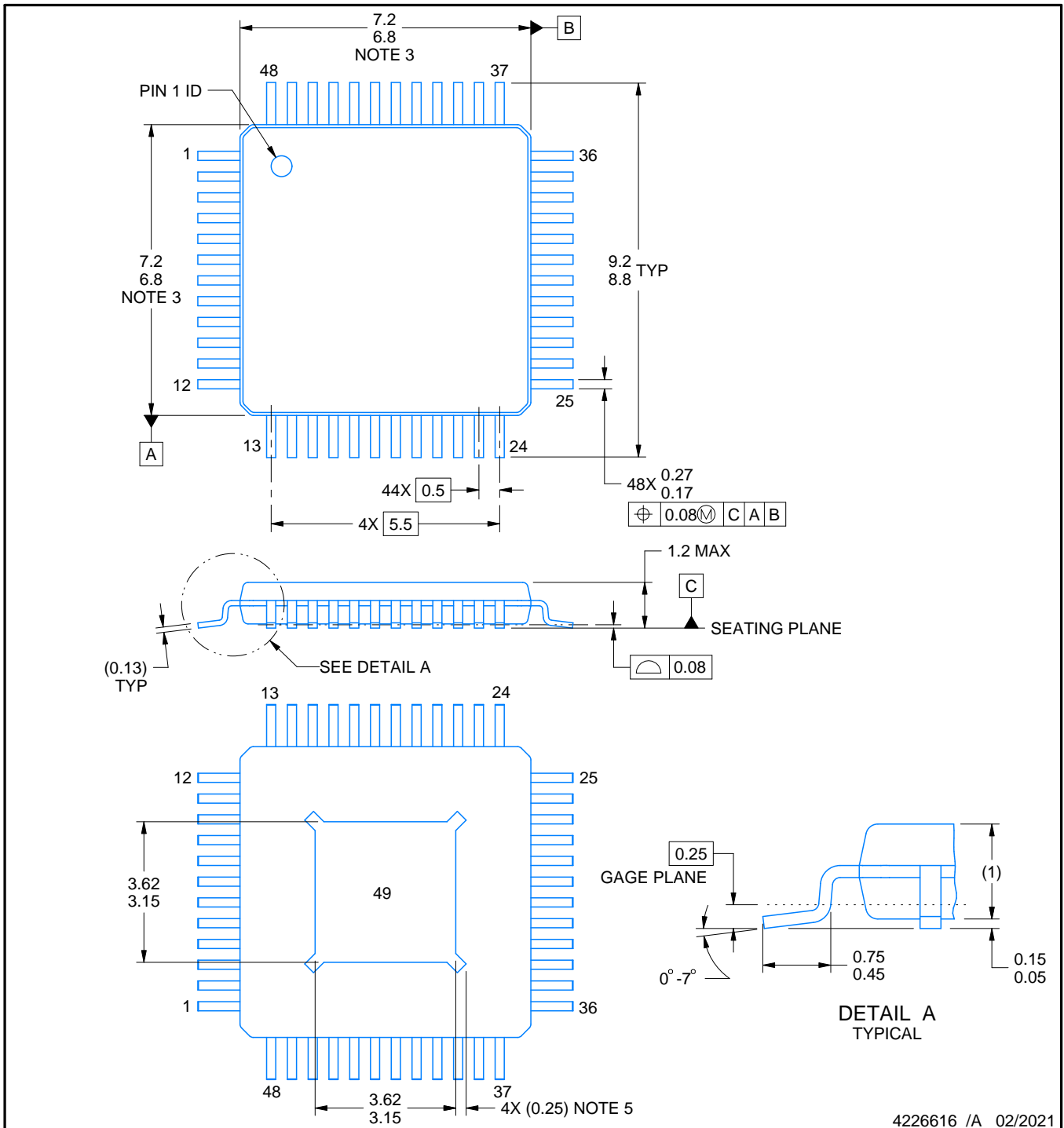
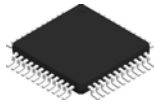
7 x 7, 0.5 mm pitch

QUAD FLATPACK

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4226443/A



4226616 /A 02/2021

NOTES:

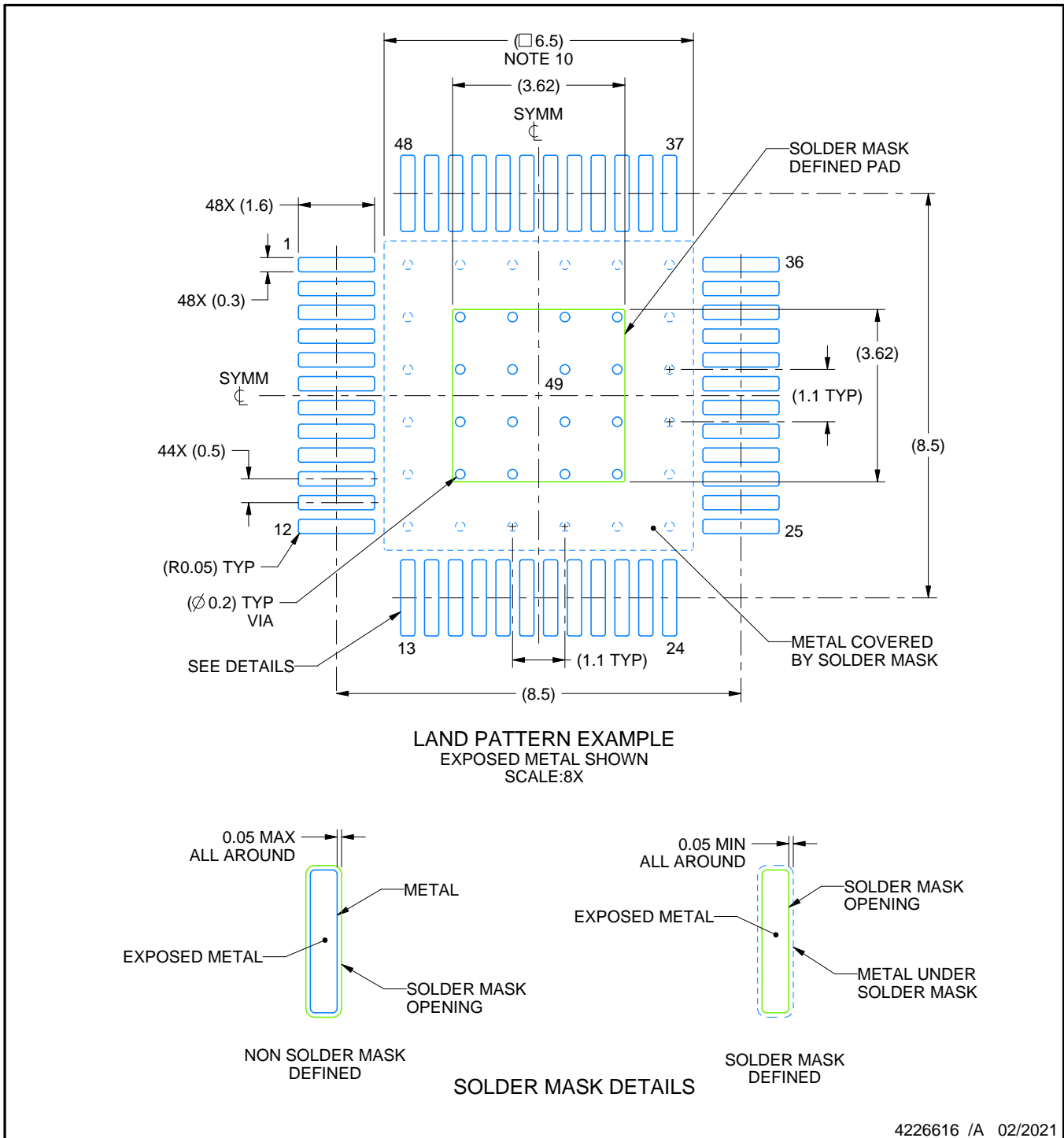
PowerPAD is a trademark of Texas Instruments.

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MS-026.
5. Feature may not be present.

EXAMPLE BOARD LAYOUT

PHP0048E

PowerPAD™ HTQFP - 1.2 mm max height



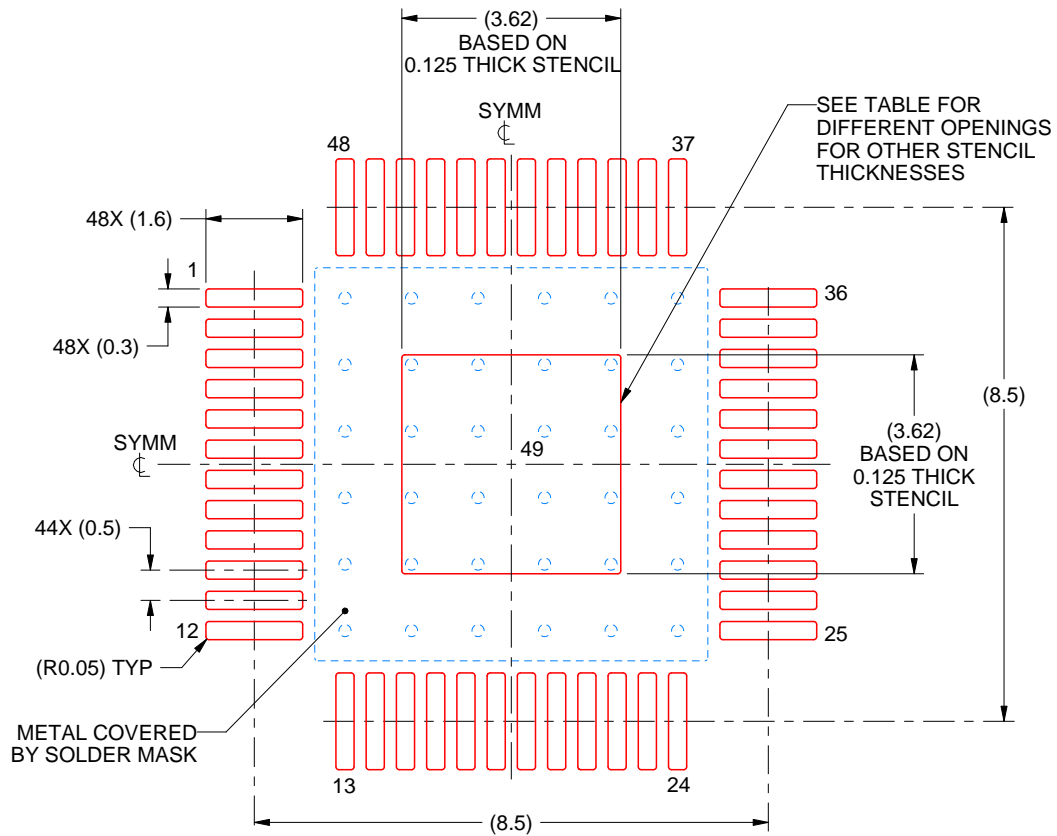
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. See technical brief, Powerpad thermally enhanced package, Texas Instruments Literature No. SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
9. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.
10. Size of metal pad may vary due to creepage requirement.

EXAMPLE STENCIL DESIGN

PHP0048E

PowerPAD™ HTQFP - 1.2 mm max height



SOLDER PASTE EXAMPLE
 EXPOSED PAD
 100% PRINTED SOLDER COVERAGE BY AREA
 SCALE:8X

| STENCIL THICKNESS | SOLDER STENCIL OPENING |
|-------------------|------------------------|
| 0.1 | 4.05 X 4.05 |
| 0.125 | 3.62 x 3.62 (SHOWN) |
| 0.150 | 3.30 x 3.30 |
| 0.175 | 3.06 x 3.06 |

4226616 /A 02/2021

NOTES: (continued)

- 11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 12. Board assembly site may have different recommendations for stencil design.

重要声明和免责声明

TI“按原样”提供技术和可靠性数据（包括数据表）、设计资源（包括参考设计）、应用或其他设计建议、网络工具、安全信息和其他资源，不保证没有瑕疵且不做任何明示或暗示的担保，包括但不限于对适销性、某特定用途方面的适用性或不侵犯任何第三方知识产权的暗示担保。

这些资源可供使用 TI 产品进行设计的熟练开发人员使用。您将自行承担以下全部责任：(1) 针对您的应用选择合适的 TI 产品，(2) 设计、验证并测试您的应用，(3) 确保您的应用满足相应标准以及任何其他功能安全、信息安全、监管或其他要求。

这些资源如有变更，恕不另行通知。TI 授权您仅可将这些资源用于研发本资源所述的 TI 产品的应用。严禁对这些资源进行其他复制或展示。您无权使用任何其他 TI 知识产权或任何第三方知识产权。您应全额赔偿因在这些资源的使用中对 TI 及其代表造成的任何索赔、损害、成本、损失和债务，TI 对此概不负责。

TI 提供的产品受 [TI 的销售条款](#) 或 [ti.com](#) 上其他适用条款/TI 产品随附的其他适用条款的约束。TI 提供这些资源并不会扩展或以其他方式更改 TI 针对 TI 产品发布的适用的担保或担保免责声明。

TI 反对并拒绝您可能提出的任何其他或不同的条款。

邮寄地址：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265

Copyright © 2024，德州仪器 (TI) 公司